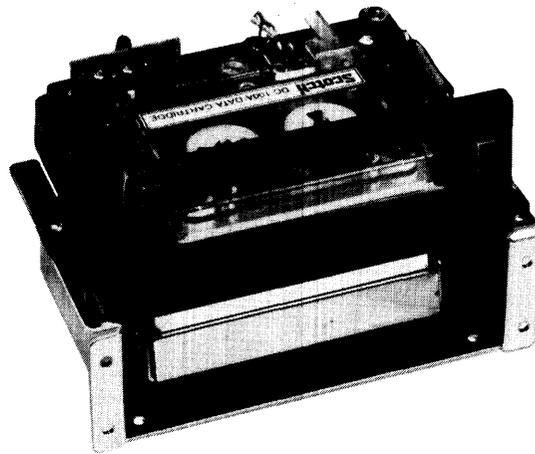


DCD-1 DATA CARTRIDGE DRIVE



INSTRUCTION MANUAL

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NOTES

SECTION I. INTRODUCTION

1-1 SCOPE

This manual describes the DCD-1 Data Cartridge Drive along with its operation, interface, use, mounting, and maintenance.

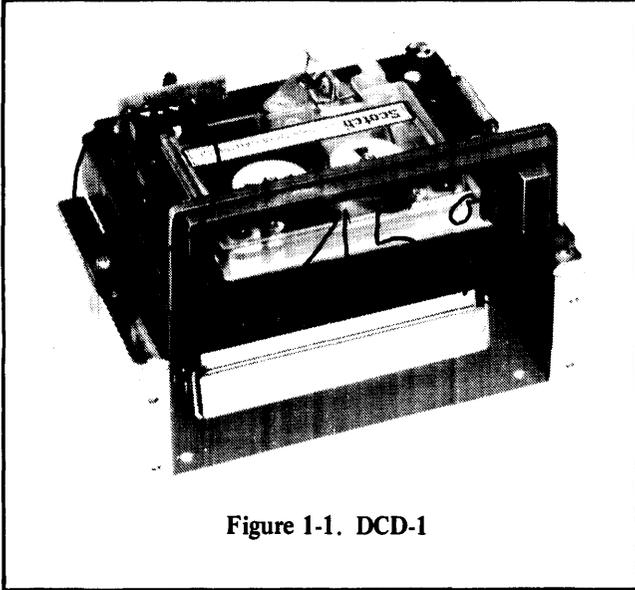


Figure 1-1. DCD-1

This manual is divided into 4 sections each of which describes specific aspects of the drive.

SECTION I. INTRODUCTION

This section provides general information and specifications for the drive system as a whole.

SECTION II. GENERAL OPERATING PROCEDURES

This section describes the mounting, interface, use and scheduled maintenance requirements of the DCD-1 Cartridge Drive.

SECTION III. SUBASSEMBLY DESCRIPTIONS

This section describes the operation of the various subassemblies which comprise a DCD-1 Cartridge Drive.

SECTION IV. PARTS LISTS, SCHEMATICS, AND PC BOARD LAYOUTS

This section contains the engineering documentation for the system.

1-2 GENERAL DESCRIPTION

The DCD-1 Data Cartridge Drive has been designed for use with the "Scotch" Brand DC100A Data Cartridge. The drive and cartridge provide a tape storage system capable of recording and reading approximately 100,000 eight bit bytes in a physically small, highly reliable unit.

The DCD-1 consists of three major subassemblies. These subassemblies are:

1-2-1 MECHANICAL ASSEMBLY

The Mechanical Assembly includes those items necessary to position and hold a cartridge within the drive, to sense the presence of a cartridge within the drive, to detect the position of the cartridge File Protect Slide Switch, and to detect the tape position holes located on the cartridge tape. The mechanical assembly also includes a motor, a tape head, and a light source used in detection of tape position holes.

1-2-2 READ/WRITE AMPLIFIER AND SERVO ELECTRONICS PC ASSEMBLY

This PC Assembly includes the circuitry necessary (1) to maintain tape speed and direction according to input command; (2) to interlock all tape motion commands with tape position status so that improper commands (such as requesting REWIND when tape is at BOT) will not cause activation of the drive motor; (3) to accept TTL Compatible Serial data to be written which places flux transitions on the tape for each change of logic state in the input; and (4) to accept low level read data from the tape head and convert it to a TTL compatible serial data which is identical to the input used when writing data.

This assembly also contains select circuitry which allows up to four units, consisting of a mechanical assembly, read/write amplifier and servo electronics PC Assembly, to be connected to one Encode/Decode PC Assembly.

1-2-3 ENCODE/DECODE PC ASSEMBLY

This assembly consists of that circuitry necessary to accept 8 bit bytes (bit parallel) as a data input and decode a serial TTL bit stream for use by the write amplifier. This assembly also accepts a serial TTL bit stream from the read amplifier and decodes an 8 bit byte read output for the user.

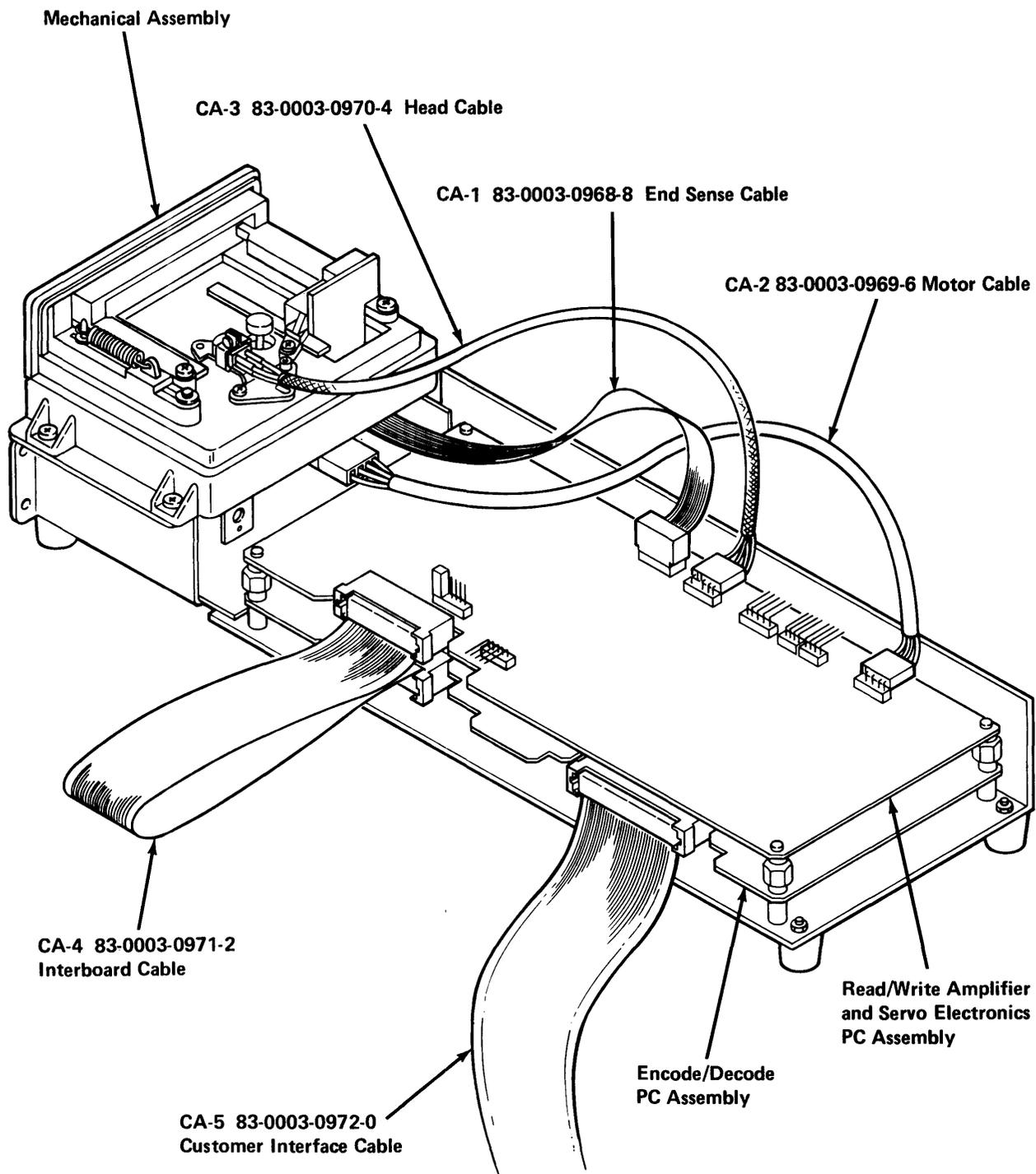


Figure 1-2. Assembly Locations

1-3 SPECIFICATIONS

The specifications of the DCD-1 Data Cartridge are as given below:

Cartridge	Uses the "Scotch" Brand DC100A Data Cartridge
Operating Speeds.	FORWARD: 30 ips (76.2 cm/s) REVERSE: 30 ips (76.2 cm/s) or 60 ips (152.4 cm/s)
Tape Head	Single channel, single gap, full width
Recording Format ^①	Variable Cell Width Recording ^②
Transfer Rate	2400 bytes/second, average
Cartridge Capacity.	102,400 bytes, average (256 bytes per block, 1 inch IRG)
Start Delay.	27 milliseconds
Stop Delay.	5 milliseconds
Interface Logic	TTL compatible
Power	+5 VDC \pm 5%, 1.5 amps; +12 VDC (+10.8 VDC to +15 VDC), 1 amp average, 3 amps peak (20 msec duration) while running; 250 ma idle
Duty Cycle.	7 start/stop operations per second maximum
Ambient Temperature	0°C to 50°C
Relative Humidity	20% to 80%, noncondensing
Size	Drive 5-3/4" wide (14.6 cm) 4" high (10.2 cm) 4-1/2" deep (11.4 cm) Electronics Two 5" x 12" cards (12.7 x 30.48 cm)
Weight.	3-1/4 pounds maximum (1.47 kg)
Finish	All metal surfaces finished per best commercial practices.

NOTES:

① See Section 3.3.2 for description.

② PATENT PENDING

SECTION II. GENERAL OPERATING PROCEDURES

Before applying power to or attempting to use the DCD-1, the user should become familiar with this section of the manual.

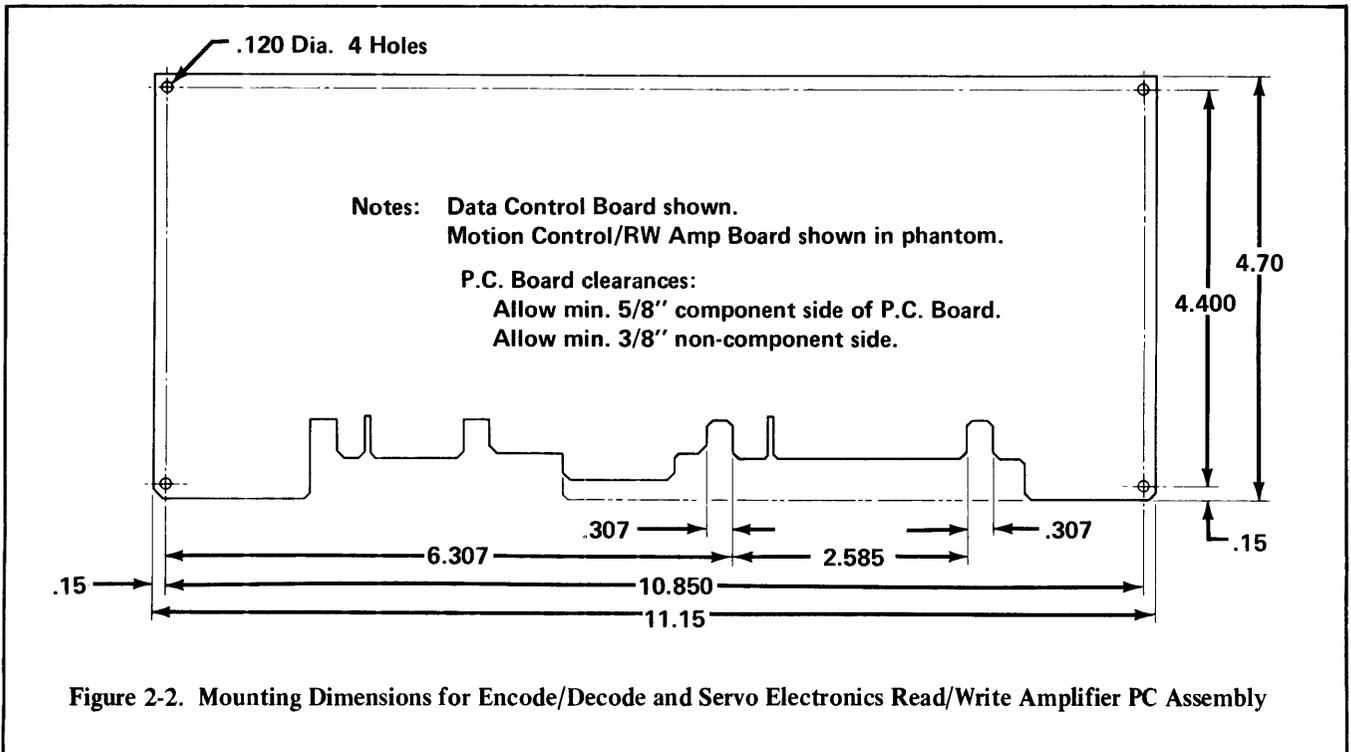
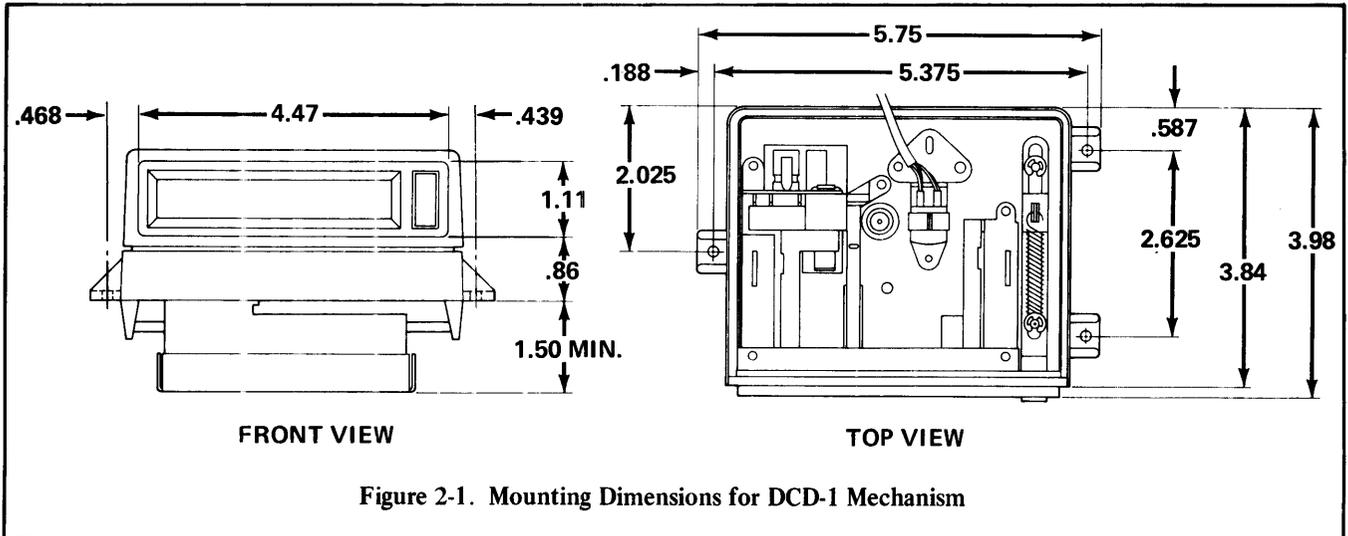
2-1 INSTALLATION

When unpackaging a DCD-1, the user should insure that the following items were received:

- 1 each* Encode/Decode PC Assembly
- 1 each* Interboard Cable
- 1 each* Interboard Connector
- 1 each* 6' Interface Cable and Connector Header
- 3 each* PC Card Power and Display Connectors
- 2 each** PC Card Power and Display Connectors
- 1 each Instruction Manual

- 1 each Mechanical Assembly
- 1 each Read/Write Amplifier and Servo Electronics PC Assembly

- * Included with master drive units only
- ** Included with slave drive units only



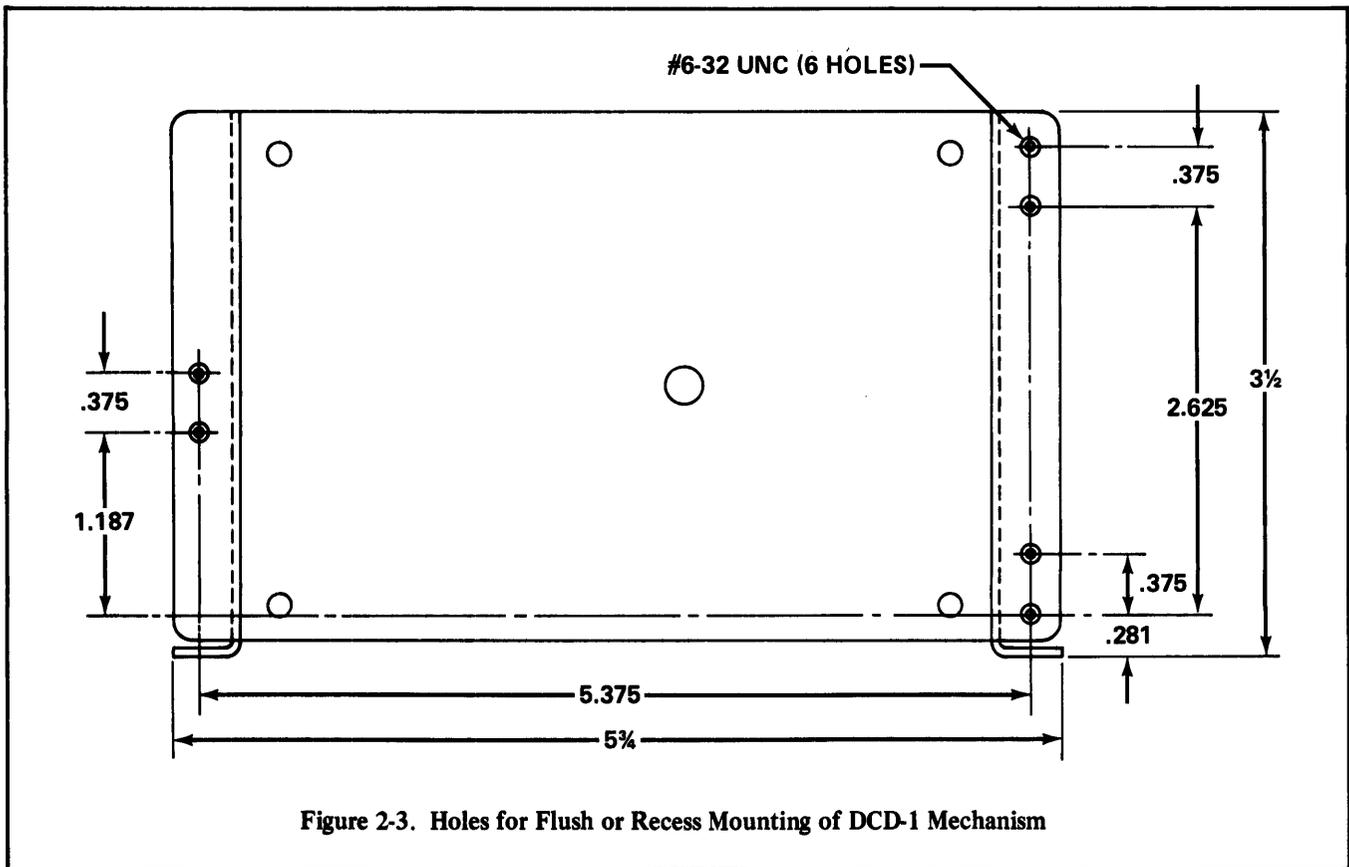


Figure 2-3. Holes for Flush or Recess Mounting of DCD-1 Mechanism

The DCD-1 mechanical assembly may be mounted in any attitude. As shown in Figure 2-1, the unit may be secured at the three ears of the top plate casting. Or if desired, the shipping bracket, used to protect the motor, may be used as a mounting frame. Location of holes for mounting in this frame are shown in Figure 2-1 and 2-2. Note that the top plate casting can be secured to the mounting frame in two different positions as shown in Figure 2-3. In the forward position, the frame can be attached to a front panel by through-bolting. In the recessed position, the frame can be attached to studs welded to the back of a front panel.

Figure 2-4 illustrates cable modification procedure for connecting one or more slave units to a master. Electrical interconnection of the three subassemblies is accomplished as shown in Figure 2-5. The two PC Assemblies may be mounted up to 12 inches away from the mechanical assembly. All connectors are keyed to prevent improper interconnection.

2-2 POWER APPLICATION

When applying power to the DCD-1, the +12 VDC power should be applied prior to application of the +5 VDC power

input. This prevents any possibility of motor movement during the power up cycle. When removing power, turn off the +5 VDC input first.

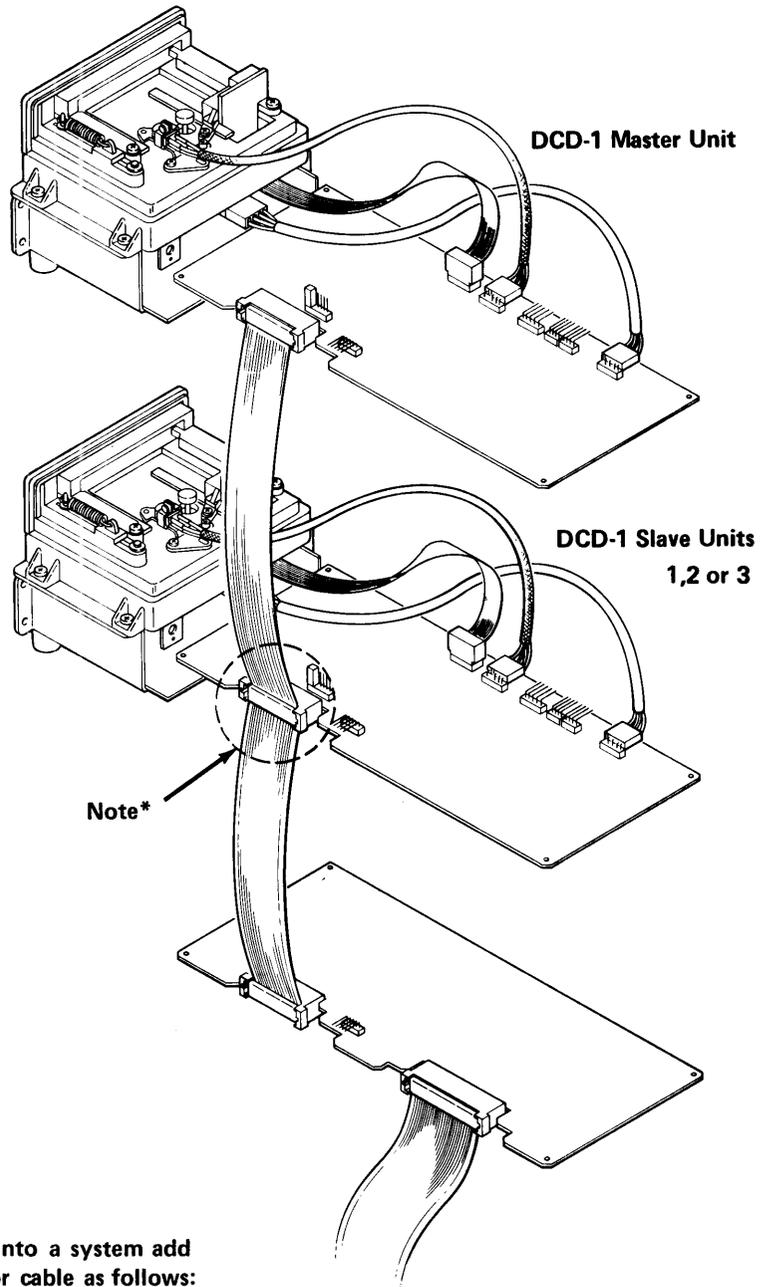
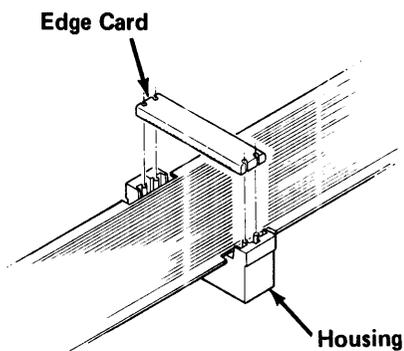
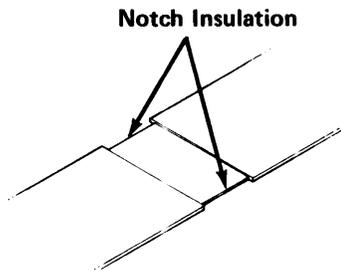
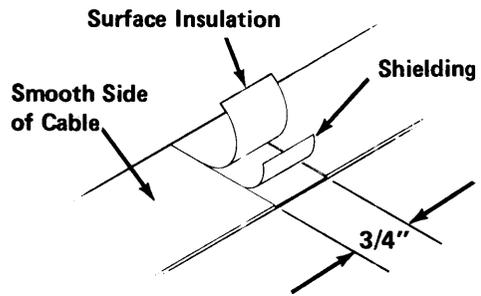
2-3 INTERFACE LOGIC

All inputs and outputs of the DCD-1 are TTL compatible with 0 to +0.8 VDC = logic 1 = low and +2.5 VDC to +5.0 VDC = logic 0 = high. The read data output is from 74125 tri-state drivers. The write data input goes directly to 74100 latches. All other outputs are from either 7416 or equivalent open collector buffer drivers. All inputs go to 7404 or equivalent gates. Except for select 0 and 1, which go to a 74155 2 line to 4 line decoder.

Recommended logic interfaces for the DCD-1 are as shown in Figure 2-6. When less than 4 feet of cable is used, the 220 ohm/330 ohm resistor terminations may be replaced with 1K ohm pull ups if desired.

2-4 INTERFACE SIGNALS

The interface signals of the DCD-1 and their functions are as described below. Details concerning the use of these signals are presented in various sections dealing with specific operations.



Note*

To connect one or more DCD-1 slave units into a system add connector kit 83-0003-1027-2 to 26 conductor cable as follows:

1. At the desired location on the cable where plug is to be added, score the insulation on the shielding side of the cable (smooth side) to enable removal of 3/4" of insulation and shielding. Peel the insulation from the shield, then peel the shield from the cable.
2. Cut sufficient amount of insulation from each side of cable to allow acceptance of the plug to be installed, taking care not to cut into edge conductors.
3. Align plug on the prepared area of the cable, smooth surface to plug connectors.
4. Compress the cable between the plug and the plug plate. (If connector tool is not available for compressing connectors on the cable, a vice may be used.) Top plate should be even with plug tabs when connector is properly seated.

Figure 2-4. Connecting One or More Slave DCD-1 Units into a System

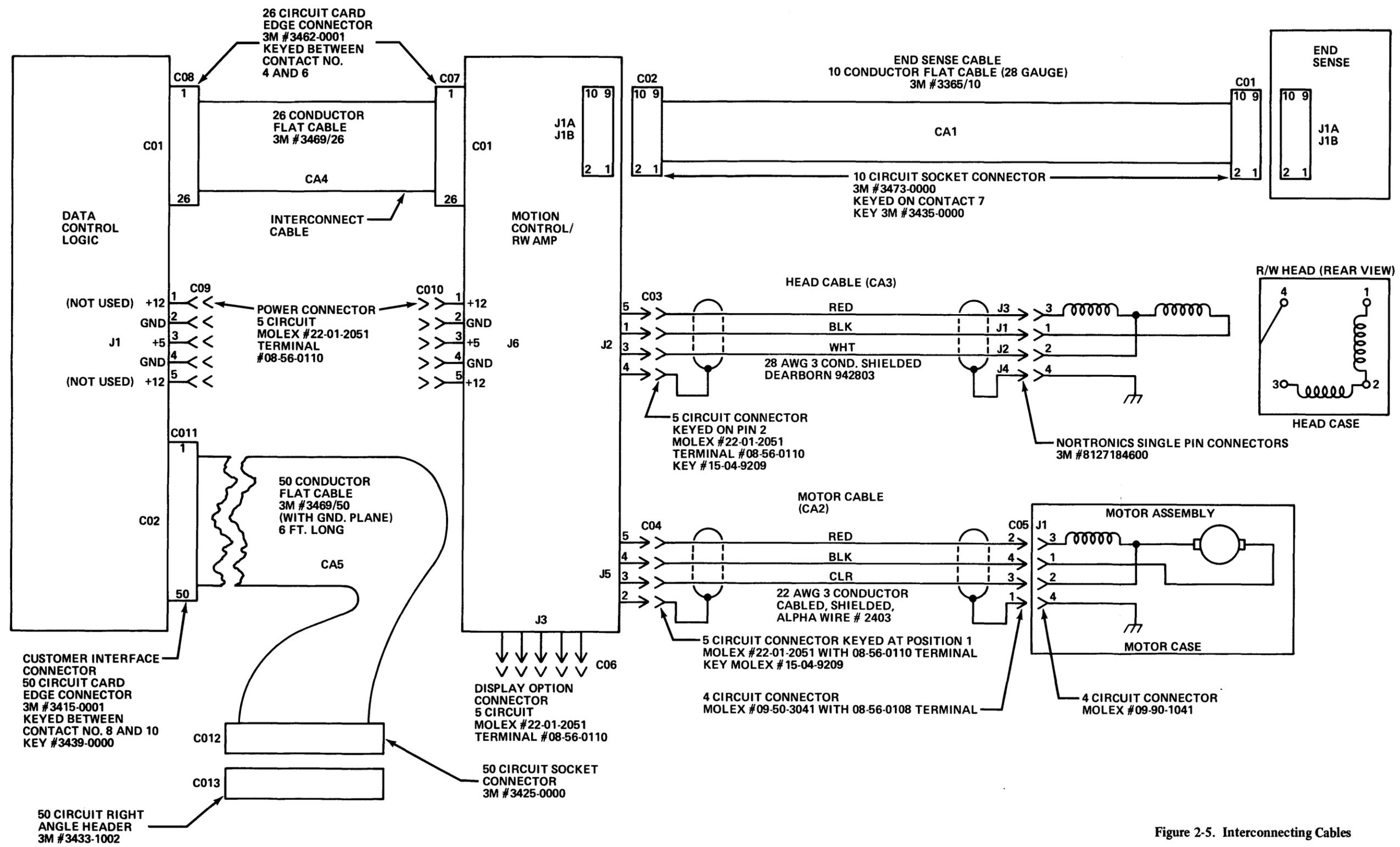
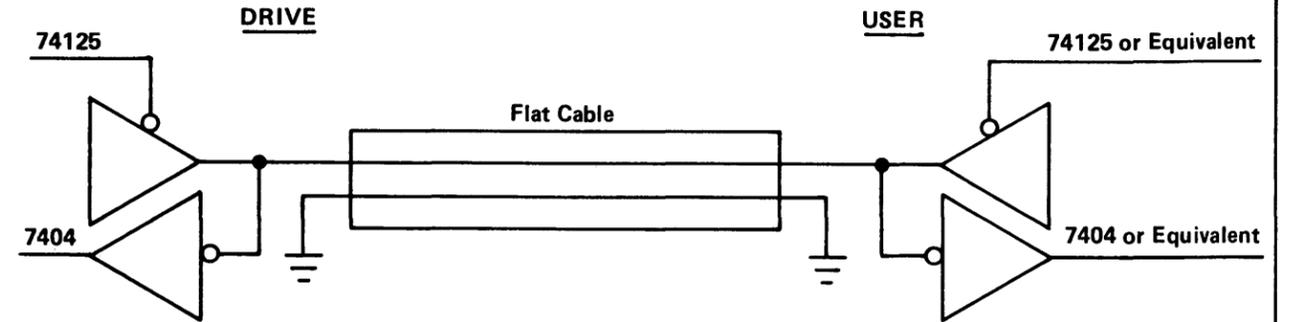
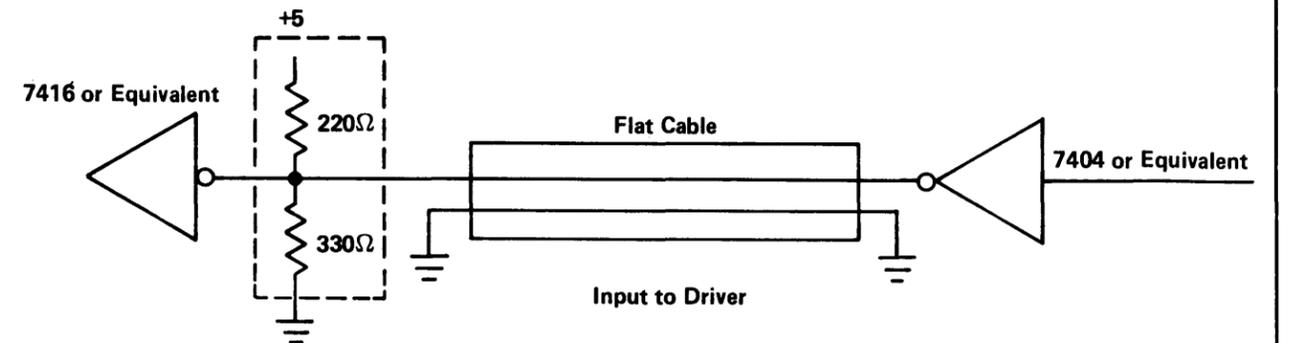
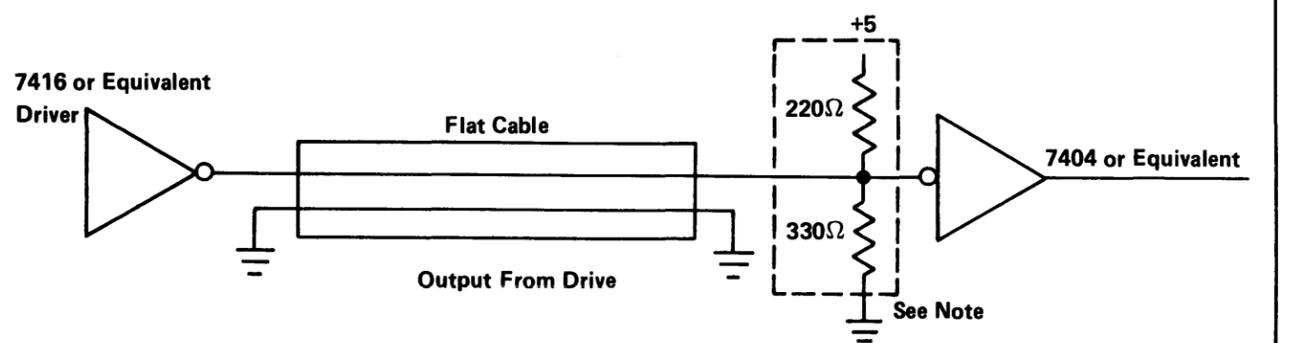


Figure 2-5. Interconnecting Cables



NOTE: For short line (<4 feet) these lines could be driven from a MOS tri-state driver. Such as is used in some microprocessor systems.



NOTE: For short lines (<4 feet) each line may be pulled up with a single 1K resistor to +5V and driven by a MOS or standard TTL output. (Remove the 220 – 330 ohm network in tape drive (RN1) and replace with a 1K network.)

Figure 2-6. Recommended Interface Circuits

2-4-1 STATUS OUTPUTS

Two lines which give data relating to tape position and operational status of the drive. These outputs are:

2-4-1-1 BEGINNING OF TAPE (BOT)

A low level output that occurs when tape is at BOT. A reverse direction motion command will not be accepted when tape is at BOT.

2-4-1-2 READY

An output that is low during read operations when tape is between LOAD POINT and EARLY WARNING. See Figure 2-8. During write operations, the cartridge file protect slide switch must be in the RECORD position and the tape must be between LOAD POINT and EARLY WARNING for READY to go low.

2-4-2 TAPE MOTION COMMANDS

The DCD-1 Data Cartridge Drive has four input lines to control tape motion. These inputs are interlocked to the various drive status and tape position outputs to prevent motions which might damage the cartridge, such as giving a reverse command when the cartridge is already at beginning of tape.

2-4-2-1 FORWARD/REVERSE (F/R)

The status of this line determines the direction of tape motion. A high level causes forward motion and a low level causes reverse motion when the RUN input pulse is applied.

2-4-2-2 RUN

A low going pulse of 500 nanosecond minimum, maximum of 200 microsecond duration on this line causes tape motion to commence in the direction determined by the state of the FORWARD/REVERSE input. Motion commences upon the low to high transition.

2-4-2-3 STOP

A low going pulse on this line of 50 nanosecond minimum duration causes tape motion to stop. The STOP input overrides the RUN input, so that if both RUN and STOP are simultaneously low no tape motion will result.

2-4-2-4 RESET

A low going pulse on this input causes the READY input to go low regardless of tape position. This line is used to clear drive logic after a power interrupt. If tape is in motion when the RESET pulse is applied, tape motion will halt. RESET should be a pulse of 500 nanoseconds minimum duration and should be held low until power is completely up. Note that RESET clears system logic and forces the READY output to the true (low) state. Consequently, improper use of the RESET input (stopping at EOT, applying a reset pulse, commanding forward tape motion, and repeating this sequence) could cause damage to the cartridge. It is therefore recommended that after applying a RESET command, the cartridge be rewound to BOT before commencing further operations.

2-4-3 SELECT 0 AND SELECT 1

These two lines are used to select the active drive in multiple drive systems according to the following table:

SELECT 0	SELECT 1	SELECTED DRIVE
High	High	0
Low	High	1
High	Low	2
Low	Low	3

2-4-4 DATA 0 THROUGH DATA 7

Eight lines which form the data bus (used in both read and write operations). DATA 0 is the least significant bit, DATA 7 is the most significant bit.

2-4-5 READ/WRITE CONTROL

A level input which controls mode of operation. This line is held low to perform a write operation (enables head current) and held high to perform a read operation. During write operations, READ/WRITE CONTROL should be set low prior to initiating tape motion and held low until tape motion ceases to insure the writing of clean inter-record gaps.

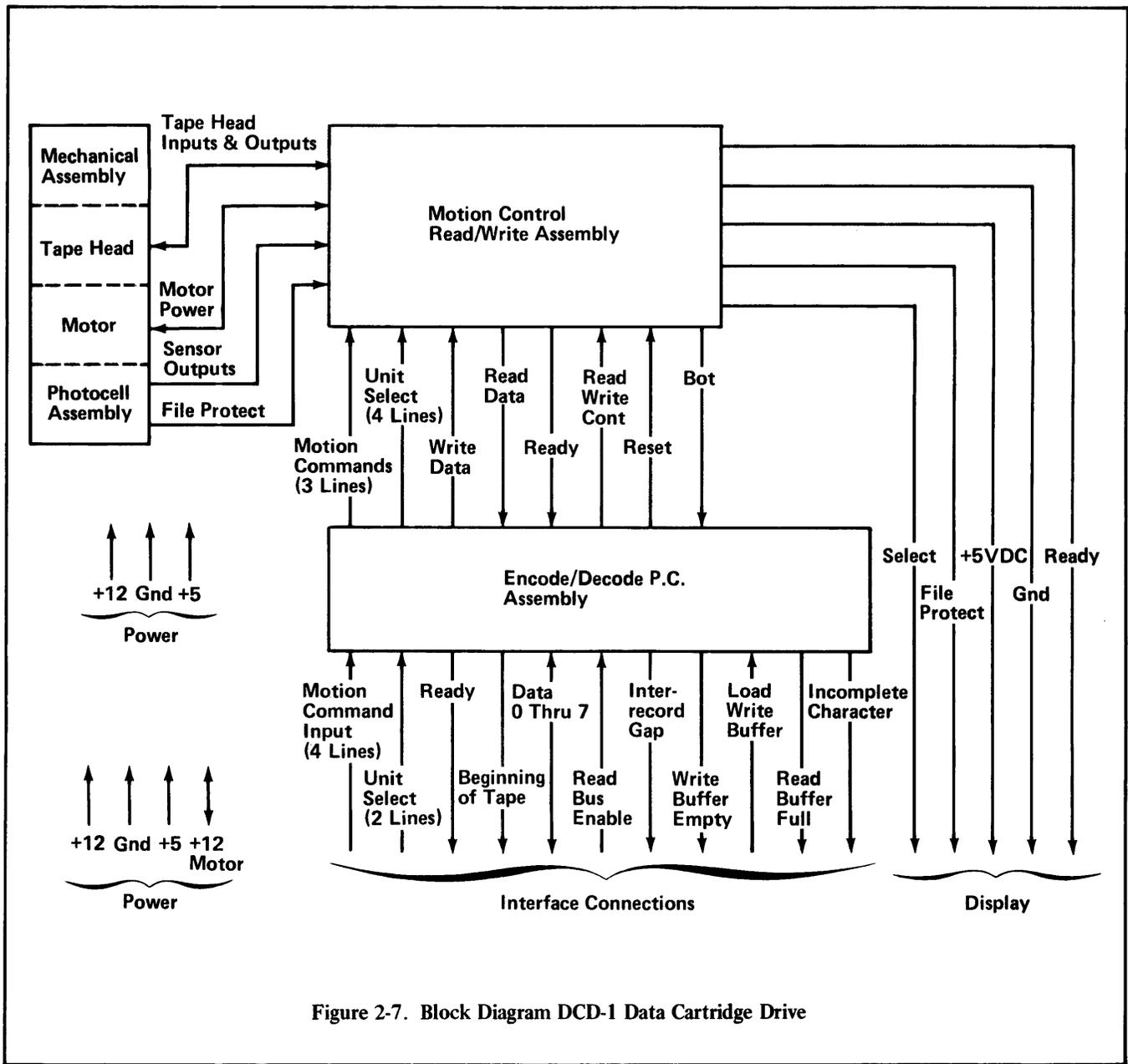


Figure 2-7. Block Diagram DCD-1 Data Cartridge Drive

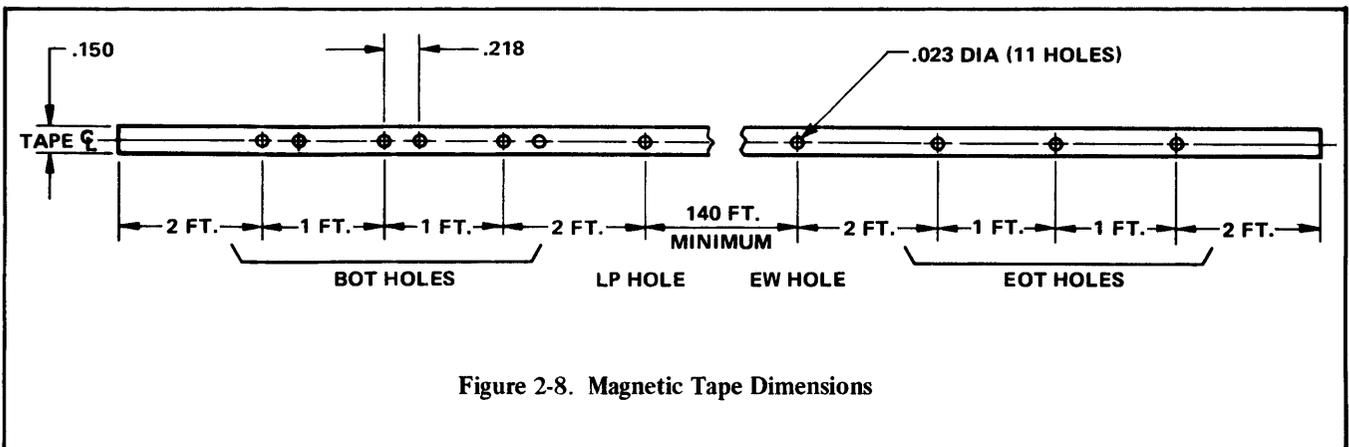


Figure 2-8. Magnetic Tape Dimensions

2-4-6 READ BUS ENABLE

When this line is pulsed low, the contents of the read buffer are shifted onto the data bus. This pulse also clears the READ BUFFER FULL and INCOMPLETE CHARACTER flags.

The READ BUS ENABLE pulse must be at least 50 nanoseconds in duration and must occur no sooner than 20 nanoseconds after READ BUFFER FULL goes low. The READ BUS ENABLE pulse must return high within 200 microseconds of READ BUFFER FULL going low to avoid missing data.

2-4-7 INTERRECORD GAP

An output that goes low each time an interrecord gap is detected. This output is active when tape is moving in either the forward or reverse direction.

2-4-8 WRITE BUFFER EMPTY

This is an output flag that goes low to indicate that the write buffer is empty and ready to accept another byte of data.

When the first byte of a block is loaded, WRITE BUFFER EMPTY will go low again within from 16.7 microseconds to 83.5 microseconds, depending upon internal logic timing. After going low for the second byte, WRITE BUFFER EMPTY will go low no sooner than every 350 microseconds.

2-4-9 LOAD WRITE BUFFER

A low going pulse on this input causes information on the data bus to be strobed into the write buffer. This pulse must be at least 500 nanoseconds but no greater than 1.5 microseconds long. (The LOAD WRITE BUFFER pulse must occur less than 320 microseconds after WRITE BUFFER EMPTY goes low.) The LOAD WRITE BUFFER pulse also clears the WRITE BUFFER EMPTY output flag.

2-4-10 READ BUFFER FULL

This is an output flag that goes low when the read buffer contains a data byte. This flag will stay low until cleared by a READ BUS ENABLE input flag. READ BUFFER FULL will go true no sooner than every 200 microseconds.

In order to discriminate against false transitions in the inter-record gap, one 8 bit byte must be read before this flag becomes active.

2-4-11 INCOMPLETE CHARACTER

This is an output flag that goes low if a complete 8 bit byte is not contained in the read buffer when the READ BUFFER FULL output goes low. All bytes containing fewer than 8 bits will result in this flag going low thus indicating an error condition caused typically by tape dropouts. In order to discriminate against false transitions in the inter-record gap, one 8 bit byte must be read before this flag becomes active. A READ BUS ENABLE pulse clears this flag; therefore the status of this flag should be checked after READ BUFFER FULL goes low but before the READ BUS ENABLE input is issued.

Table 2-2. DCD-1 Power Connector Pin Assignments (SERVO ELECTRONICS AND READ/WRITE AMPL PC ASSEMBLY)

Pin	Function
1	+12 VDC 10.8 VDC to 15.0 VDC, 1 Amp Avg. 3 Amps Peak (20 msec duration) while running; 250 ma idle
2	Ground
3	+5 VDC $\pm 5\%$, 0.5 amps
4	Ground
5	+12 VDC

Table 2-3. DCD-1 Power Connector Pin Assignments (ENCODE/DECODE PC ASSEMBLY)

Pin	Function
1	+12 VDC (Not Used)
2	Ground
3	+5 VDC $\pm 5\%$ 1.5 Amps
4	Ground
5	+12 VDC (Not Used)

Logic interface connection to the DCD-1 is via a 50 pin, PC card edge connector, "Scotchflex" No. 3415-0001 or equivalent, keyed between contacts 8 and 10. For "Scotchflex" connectors, use key No. 3439-0000.

Power connection is via two Molex connectors, No. 22-01-2051 with contacts No. 08-56-0114. One connector is used for each PC card.

Table 2-4. Interface Connector Pin Assignments

Function	Pin
Run	2
Load Write Buffer	4
Select 0	6
Select 1	8
Read/Write Control	10
Forward/Reverse	12
Reset	14
Stop	16
Read Bus Enable	18
Ready	20
Write Buffer Empty	22
Interrecord Gap	24
Incomplete Character	26
Read Buffer Full	28
Beginning of Tape	30
Not Used	32
Not Used	34
Data 0	36
Data 1	38
Data 5	40
Data 4	42
Data 2	44
Data 3	46
Data 7	48
Data 6	50
Common	All Odd No. Pins 1-49

2-5 CARTRIDGE LOADING

Loading the cartridge requires inserting a cartridge into the drive and positioning tape at Load Point.

The cartridge is installed in the drive by inserting it into the rectangular slot in the drive facade. With respect to the top plate, the cartridge is inserted with its metal base plate next to the drive top plate and with the cartridge edge containing head door and belt capstan being inserted first (this is the only cartridge orientation that will permit cartridge loading). The cartridge should be pushed fully into the drive; an audible click will be heard and the EJECT button protrudes from the front of the mechanism when the cartridge is engaged by the drive. Should difficulty be encountered, be sure the EJECT button is fully depressed before inserting the cartridge. To remove a cartridge from the drive, depress the EJECT button on the front facade of the drive.

Once the cartridge has been inserted into the drive, the first command issued must be for reverse motion (this is the

only command that will be accepted until BOT is reached). When tape motion stops at BOT, command forward motion until Load Point is reached (the READY output will go true). The drive and cartridge are now initialized and ready for subsequent read/write operations.

It is recommended that an initial gap of 7-1/2 inches or longer be used between the LOAD POINT hole and the first data record. (Approximately 275 ms delay following the READY signal at LOAD POINT will produce this initial gap.)

2-6 INTERRECORD GAP TIMING

To insure the writing of proper length interrecord gaps, the following delays should be employed:

- (a) After commanding forward tape movement, delay 27 milliseconds before entering the first data byte.
- (b) After writing (or reading) the last data byte, delay 5 milliseconds before commanding a STOP. During read operations, the INTERRECORD GAP output indicates the end of a data block.

2-7 WRITING A DATA BLOCK

When writing data, the following sequence of events should be used:

1. Set the READ/WRITE CONTROL input to the low logic state.
2. Check the READY output (assuming that tape is between LOAD POINT and EARLY WARNING). If it is low, proceed. If it is high, remove the cartridge, place the file protect slide switch in the RECORD position, reinsert the cartridge, set READ/WRITE CONTROL high, rewind to BOT, come forward until READY goes low, stop tape motion, and commence operation again at Step 1.
3. Set the FORWARD/REVERSE input high.
4. Apply a pulse to the RUN input.
5. Delay 27 milliseconds during which time the first byte to be written should be placed on the data bus.
6. After 27 milliseconds apply a LOAD WRITE BUFFER pulse.
7. Monitor the WRITE BUFFER EMPTY output. When this output goes true place the next byte to be writ-

ten on the data bus and issue another LOAD WRITE BUFFER pulse. Continue this process until all required bytes have been written.

8. Five milliseconds after the last LOAD WRITE BUFFER input, apply a STOP pulse.
9. Allow 20 milliseconds for tape motion to stop.
10. If the next operation to be performed is a write, leave READ/WRITE CONTROL low. If a read or rewind is to be performed next, set READ/WRITE CONTROL high.

2-8 READING DATA

The reading of data is accomplished per the following procedure:

1. Set the FORWARD/REVERSE input high.
2. Apply a pulse to the RUN input.
3. Apply a pulse to the READ BUS ENABLE input to clear the READ BUFFER FULL and INCOMPLETE CHARACTER flag circuits. This pulse should occur within 20 microseconds of the RUN pulse.
4. Monitor the READ BUFFER FULL output. For the first byte, it will go low about 27 milliseconds after the RUN pulse is applied. Thereafter it will go true approximately every 350 microseconds.
5. When READ BUFFER FULL goes low check the level of the INCOMPLETE CHARACTER output to determine if an error has occurred.
6. Set the READ BUS ENABLE input low. The data byte will have settled on the data bus within 50 nanoseconds of this input. Read data is only on the bus as long as this input is low.
7. After the byte has been captured by the user's circuitry, set READ BUS ENABLE high.
8. Alternate between monitoring the READ BUFFER FULL and INTERRECORD GAP flags.
9. If READ BUFFER FULL goes low, return to Step 5.
10. If INTERRECORD GAP goes low, wait 5 milliseconds and apply a pulse to the STOP input. Wait 20 milliseconds for tape motion to stop before issuing further commands. A continuous read is accomplished by not issuing the STOP pulse.

Table 2-5. Display Connector Pin Assignments

FUNCTION	SYMBOL USED ON SCHEMATIC	PIN
Select	SEL	1
+5 VDC	+5 VDC	2
File Protect	FP	3
Ground	GND	4
Ready	RDY	5

2-9 DRIVE UNIT SELECTION

As noted in paragraph 1-2-2, the DCD-1 is available in multiple drive configurations. When 2 or more drives are present, the SELECT 0 and SELECT 1 inputs must be used to determine which drive shall be operative during execution of a given function. Selection is accomplished according to the following table:

Table 2-6. Drive Unit Selection

DRIVE	SELECT 0	SELECT 1
0	High	High
1	Low	High
2	High	Low
3	Low	Low

2-10 RECOMMENDED MAINTENANCE

The only periodic maintenance required on the DCD-1 is cleaning of the tape head and motor drive roller.

These items should be cleaned with ethyl alcohol and a cotton swab every 1,000 to 1,500 cartridge cycles. A cycle is defined as tape movement from BOT to EOT and back to BOT.

In harsh environments cleaning may be required more frequently.

SECTION III. SUBASSEMBLY DESCRIPTIONS

3-1 MECHANICAL ASSEMBLY

3-1-1 DESCRIPTION

The Mechanical Assembly consists of those items necessary to position and hold a cartridge for READ/WRITE OPERATION, to apply rotary power to the cartridge bolt capstan to create motion, to detect the presence of a cartridge within a drive, to determine the status of the cartridge file protect plug, and to detect the tape position holes of the cartridge.

The major components of the assembly are the top plate, the motor-tachometer, the tape head, and the photocell amplifier PC Assembly.

3-1-2 MAINTENANCE

3-1-2-1 HEAD AND PUCK CLEANING

The only periodic maintenance required on the mechanical assembly is cleaning of the tape head and the drive puck. This cleaning operation should be accomplished every 1,000 – 1,500 tape cycles. In harsh environments, cleaning on a more frequent basis may be required.

Cleaning should be accomplished with a cotton swab moistened with ethyl alcohol by gently rubbing the head and then the drive puck.

NOTE

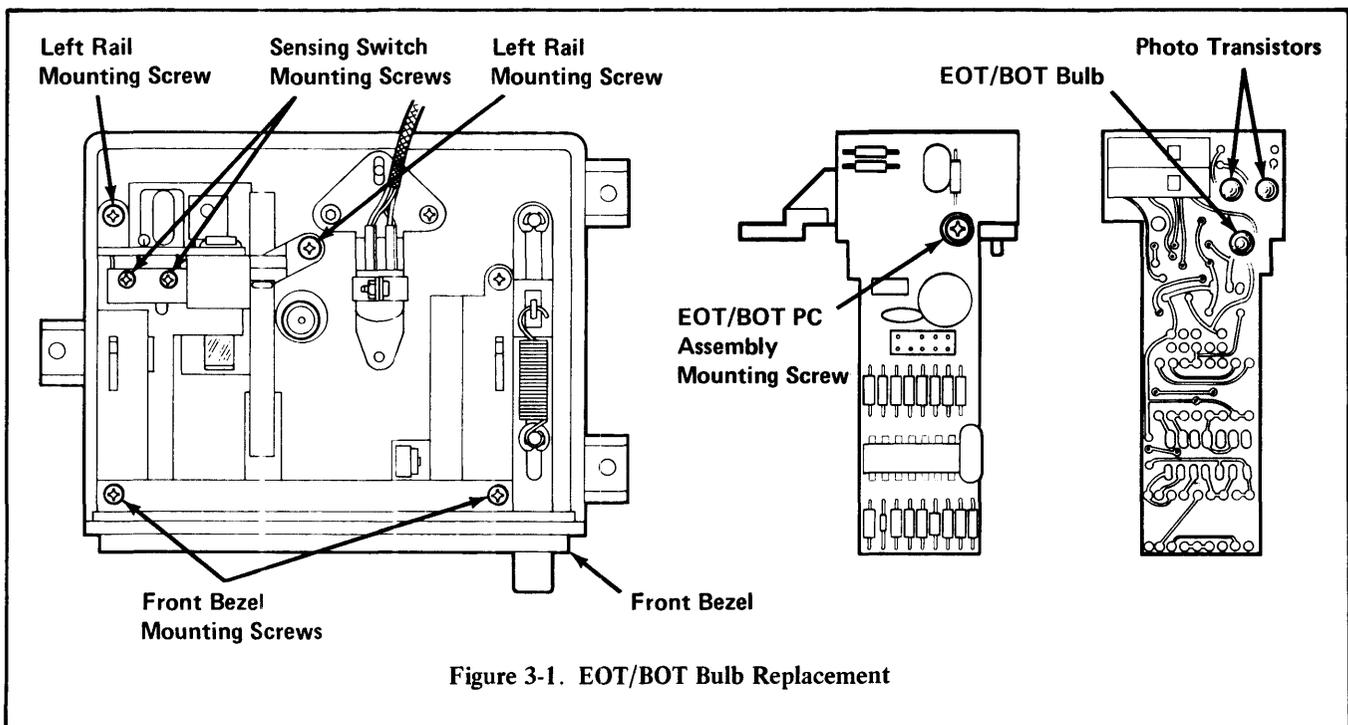
The useful life of the DCD-1 Data Cartridge Drive is estimated at 40,000 tape cycles. At this point, the head and/or motor may be near failure, and the user may elect to change these components.

It is recommended, however, that only the volume user with formalized depot programs and facilities attempt to replace these components in the Mechanical Assembly. Other users are advised to return the unit to the factory for replacement of these items.

Replacement of the EOT/BOT bulb is the one procedure which does not require specialized tools and fixtures.

3-1-2-2 EOT-BOT BULB REPLACEMENT

1. Remove the two front bezel mounting screws.
2. Remove the front bezel.
3. Unplug the cable from the EOT/BOT PC Board.
4. Remove the two rail mounting screws (left rail).



5. Remove the left rail and the EOT/BOT PC Assembly from the mechanism.
6. Remove the two sensing switch mounting screws.

CAUTION

Hex nuts are free in block depression.

7. Remove Phillips mounting screw and plastic insulation washer from the EOT/BOT PC Assembly.
8. Remove the EOT/BOT PC Board and switch assembly from the block.
9. Unsolder the old bulb from the board and clean the solder from the holes.
10. Place the new bulb leads through the holes and insert the bulb fully into the block as the PC board is again fitted to the block. Secure with the Phillips mounting screw and insulating washer.
11. Solder bulb leads with the bulb located all the way into the block.
12. Reverse the disassembly procedure from Step 6 through Step 1.

3-1-2-3 MOTOR REPLACEMENT

See Figure 3-2

1. Remove the deck from the mounting base.
2. Remove the power cable from the motor.
3. Remove the two motor pivot mounting screws.
4. Remove the motor assembly. Retain the pivot pins.
5. Insert the pivot pins into the new motor mounting.
6. Remount the motor using the screws and pivot hold down clamps.
7. No end play is permissible in the motor pivot mount. Secure one pivot clamp and force the other pivot pin into the motor mount, tighten the second pivot clamp. If end play is not completely removed, loosen one pivot clamp and force the pivot pin in, then re-tighten the clamp screw.

See maintenance section for motor control alignment procedure.

8. Whenever a motor is replaced the Servo Electronics **MUST BE REBALANCED.**

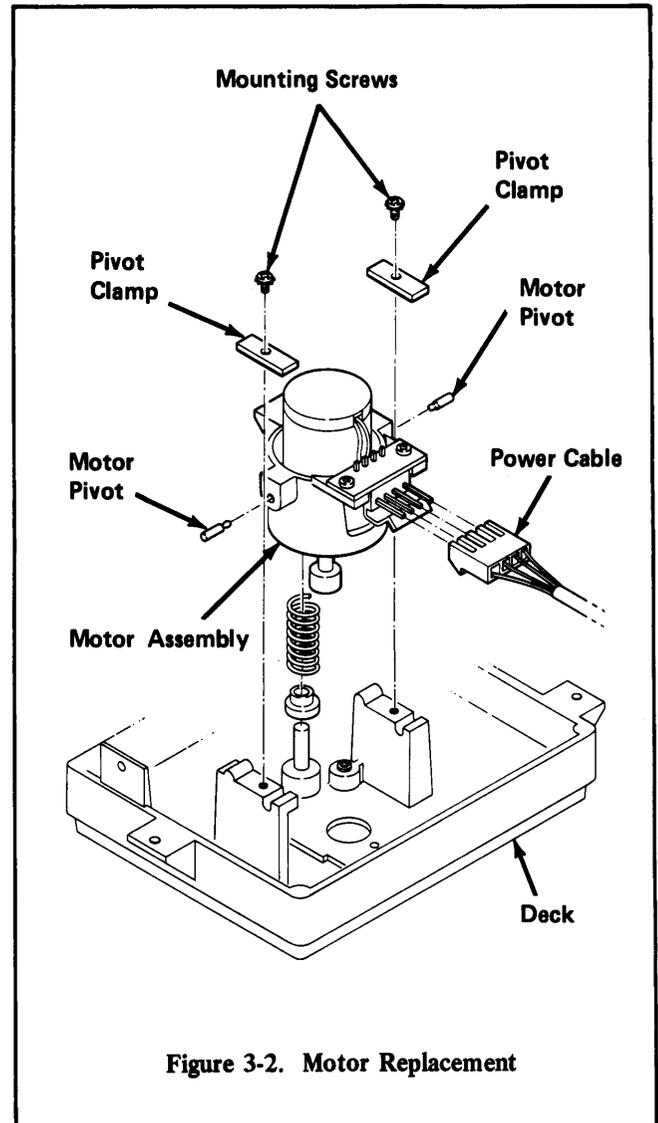


Figure 3-2. Motor Replacement

3-1-2-4 HEAD REPLACEMENT

See Figure 3-3

1. Loosen the head clamp screw sufficiently to allow the head to be removed.
2. Be sure the new head has one wrap of mylar tape around the body of the head to give insulation between head and the mounting bracket.

3. Slide the new head into place and tighten the mounting screw lightly so that head position can be changed with finger pressure.
4. Position the head so that the head will push the tape .055" to .065" into the cartridge when a cartridge is inserted fully into the deck. This may be done by measuring the distance from when the head first contacts the tape as a cartridge is inserted, and when the cartridge is firmly in position.
5. Align the two mating surfaces of the head clamp and tighten the head clamp firmly.
6. Install an azimuth alignment cartridge into the drive and adjust the azimuth screw for maximum output at TP3.

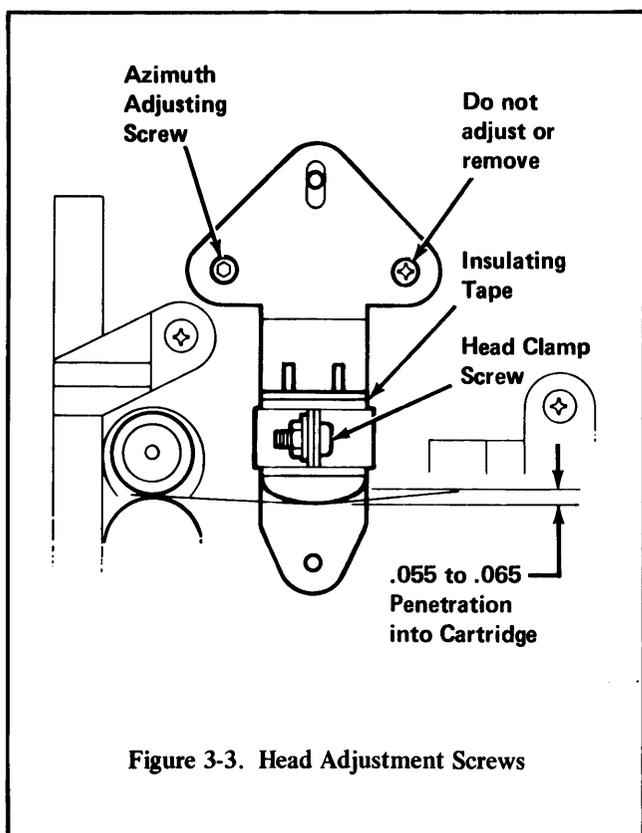


Figure 3-3. Head Adjustment Screws

3-2 SERVO ELECTRONICS AND READ/WRITE AMPLIFIER PC ASSEMBLY

This assembly is comprised of the major subfunctions listed below. See Block Diagrams, Figure 3-4 and 3-5.

3-2-1 DRIVE SELECT LOGIC

This circuitry consists of the select jumper plug which enables only the selected drive command input gates and output gates.

3-2-2 DIRECTION CONTROL LOGIC

This circuitry is comprised of two sections.

1. The Status Logic section monitors cartridge related factors such as tape position, file protect status, and cartridge in place status.
2. The Command-Status Interlock section prevents acceptance of motion commands which could harm the cartridge (rewinding from BOT, etc.).

3-2-3 SERVO ELECTRONICS

This circuitry consists of several sections which operate in unison to control the direction and speed of tape motion (by controlling motor input voltage).

3-2-4 WRITE CIRCUITRY

This circuitry consists of a write enable transistor switch which only permits head current to flow when the READ/WRITE Control input is low, and the write head drivers.

3-2-5 READ CIRCUITRY

This circuitry consists of Operational Amplifiers for Read, Threshold Detector, and Peak Detector.

3-2-6 DRIVE SELECT LOGIC

See Figures 3-4 and 3-5

One of four ENABLE inputs is connected through a jumper plug at connector J8 to IC16, pin 9. This signal is routed through 2 inverter stages and then enables negative and gates for input signals (RUN, STOP, READ/WRITE CONTROL, WRITE DATA, FORWARD/REVERSE, and RESET). The same signal also enables tri-state gates for output signals (BOT, READY, and READ DATA). The signal at IC16, pin 8 is also inverted to provide a SELECT output at IC20, pin 2. This output can sink 40 ma at +5 VDC.

3-2-6-1 LOGIC INTERFACE CONNECTIONS

The interface connections of the drive select logic portion of the read/write amplifier and servo electronics PC Assembly and their use is as described below:

3-2-6-2 ENABLE 0, 1, 2 AND 3

One to four drives may be used in a system. Selection of one of four drives is performed on the data control logic PC

Electronic Assembly. This will hold either EN 0, EN 1, EN 2, or EN 3 to ground and thereby selects the proper drive.

3-2-6-3 UNIT DESIGNATE

J8 requires a jumper plug to select the proper drive. Place the jumper plug in the 0 position when only one drive is used. When multiple drives are used designate the drive number by placing the jumper plug in positions 0, 1, 2, or 3.

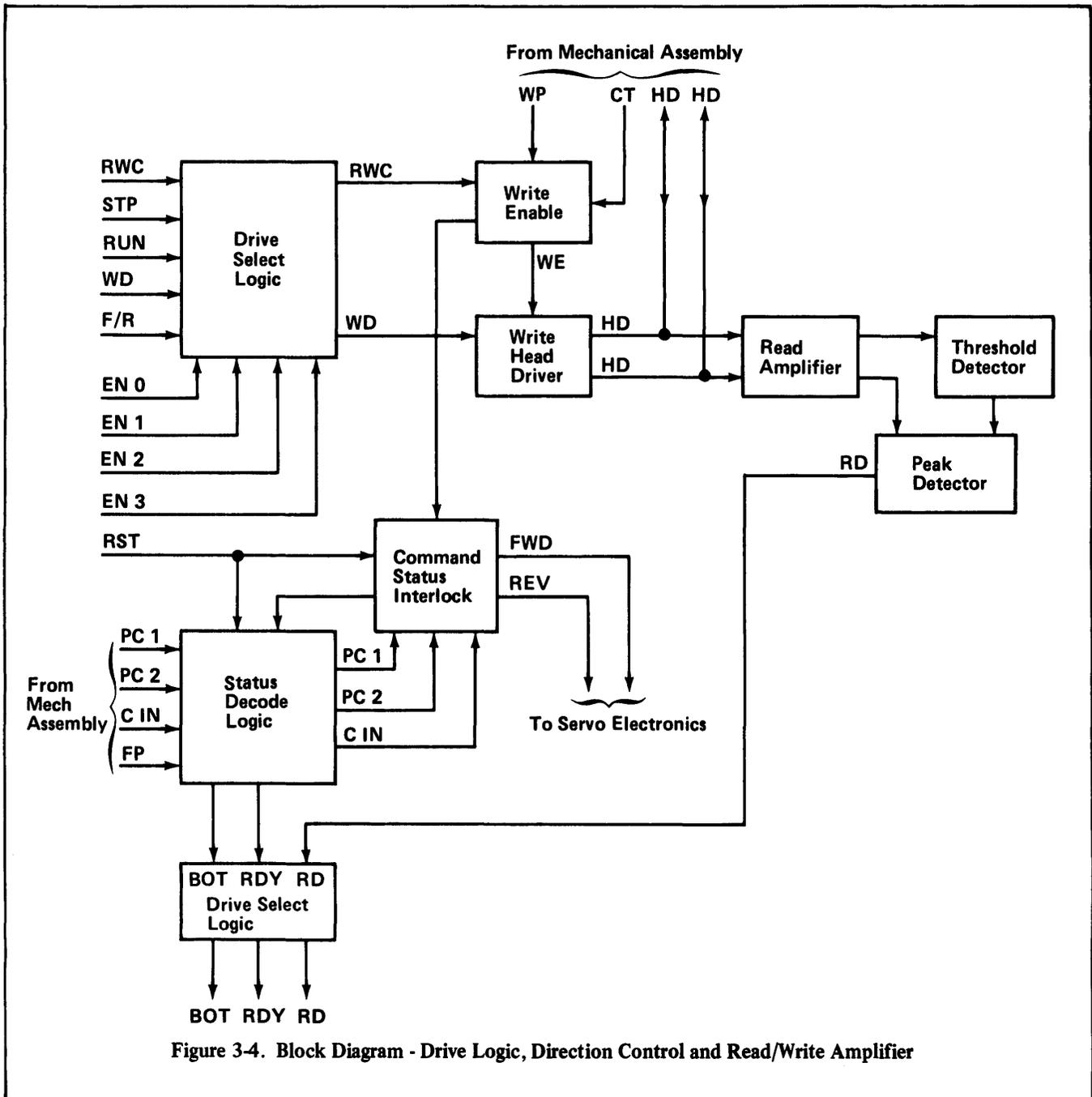


Figure 3-4. Block Diagram - Drive Logic, Direction Control and Read/Write Amplifier

3-2-6-4 FORWARD/REVERSE

The status of this line determines the direction of the tape motion. A high level causes forward motion while a low causes a reverse motion when the RUN input pulse is applied.

3-2-6-5 RUN

A low going pulse on this line of 500 nanosecond minimum duration causes tape motion to commence in the direction determined by the status of the command input. Motion commences upon the low to high transition.

3-2-6-6 STOP

A low going pulse of 500 nanosecond minimum, maximum of 200 microsecond duration on this line causes tape motion to commence in the direction determined by the state of the FORWARD/REVERSE input. Motion commences upon the low to high transition.

3-2-7 STATUS DECODE LOGIC

3-2-7-1 CARTRIDGE IN (CIN)

A switch on the mechanical assembly senses the presence of the data cartridge. When the cartridge is out this line clears the 4 bit bidirectional shift register (IC3) and sets the set/reset flip flop (IC10) to the initialization state.

3-2-7-2 PHOTOCELL 1 (PC1)

An input from the Photocell Amplifier PC Assembly. Momentarily high when a hole passes by the Photosensor. Used along with Photocell 2 to develop the various tape position outputs. A hole in the tape passes by Photocell 1 before Photocell 2 when the tape is moving in the forward direction.

3-2-7-3 PHOTOCELL 2 (PC2)

An input from the Photocell Amplifier PC Assembly. Momentarily high when a hole passes by the Photosensor. Used with Photocell 1 to develop the various tape position outputs.

3-2-7-4 FILE PROTECT

An input from the file protect switch of the photocell amplifier PC Assembly. During write operations the file protect switch on the DC100A Cartridge must be in the record position. If it is not in the Record position and RWC (Read/Write Control) is forced true, RDY will go false indicating the drive is not in the proper mode for writing. Forward and reverse motion can still take place with RDY false, but no writing will occur since the write current is disabled whenever the record switch on the DC100A is not in the record position.

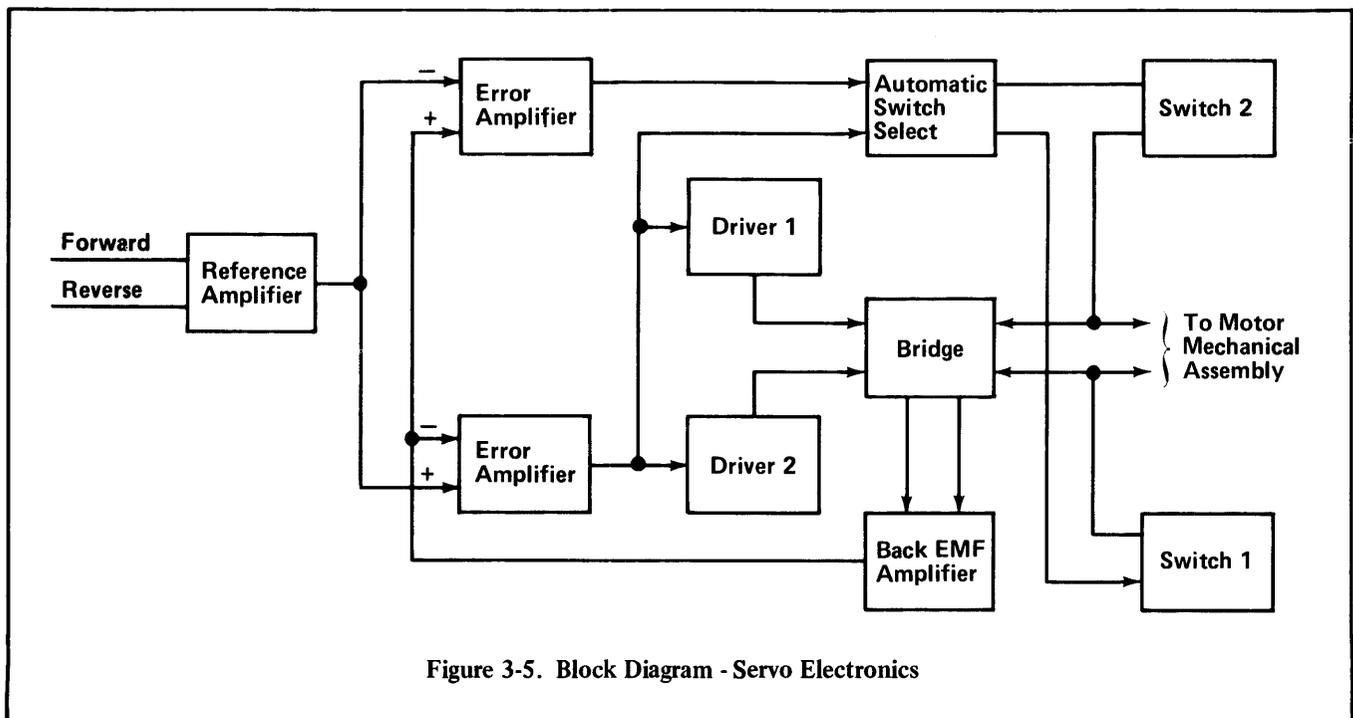


Figure 3-5. Block Diagram - Servo Electronics

3-2-7-5 RESET (RST)

A low going pulse on this line forces the status decode logic to the Ready (RDY) state regardless of actual tape position. In the ready state either Forward or Reverse Commands will be accepted. Reset Commands should be used in only these cases.

1. If it can be determined, the tape in the DC100A is actually between LP and EW. The determination of this fact would have to be based on past cartridge history.
2. To determine whether or not a cartridge is actually in the drive. A Reset Command will have no effect if there is no cartridge in the drive. Thus, issuing a Reset Command and sensing ready indicates the presence of a cartridge. A Reverse Command to BOT should then be given to properly locate the cartridge.

Using of Reset during power fail restart situation: When power restart occurs the reset line should be held true until power is stable. Appropriate action can then be taken depending on the cartridge tape position before the power failure occurred.

3-2-8 COMMAND-STATUS INTERLOCK

The command status interlock circuitry utilizes the four unique locations on the tape which are determined by the punched holes on the DC100A Cartridge. See Figure 2-8. These positions are Beginning of Tape (BOT), Load Point (LP), Early Warning (EW), and End of Tape (EOT). The photosense and direction control logic use these tape positions to generate the two drive status indications BOT and RDY. In the Forward direction, RDY is true between (LP) and (EW). At (EW) in the forward direction RDY will go false. Drive motion in the forward direction can continue until (EOT) is sensed. At (EOT) all forward motion is inhibited and any attempt to command forward motion at (EOT) is ignored. In the reverse direction, RDY is true between (EW) and (LP). At BOT, RDY will go false and BOT will go true. When BOT is true all reverse motion is inhibited and any attempt to command reverse motion is ignored. The forward and reverse commands are captured by the run command flip flop (IC2). This flip flop is conditioned by the F/R input and is clocked by the run input. The output of this flip flop controls the mode of the 4 bit bidirectional shift register. (i.e. In forward the status bit is shifted to the right, in reverse the status bit is shifted to the left.)

The forward and reverse lines to the servo (IC11 pin 6 is forward, IC6 pin 4 is reverse) are controlled by the command flip flop and are gated by the appropriate status

signals to produce proper tape motion. (This gating mainly takes place in IC12).

Forward = (Forward Command · (PC1 · PC2 + 7 ms one shot) · RUN · EOT · INIT)

Reverse = (Reverse Command · (PC1 · PC2 + 7ms one shot) · RUN · BOT)

The two one shots (IC1) are used for determining whether the photosensors are detecting the status holes in the tape or sensing whether the tape has run off the end in the cartridge. This is accomplished by the 7 ms and 15 ms timing. IC10 is an initialization flip flop. It sets on COT, which blocks all forward motion, resets on BOT or RST.

3-2-9 SERVO ELECTRONICS

The servo electronics consists of Reference Amplifier, Back EMF Amplifier, Switch Select, Switches, Error Amplifiers, and Drive Amplifiers. The Reference Amplifier provides speed reference voltage and proper voltage waveform for acceleration and deceleration on command from the Motion Control circuitry. The Back EMF Amplifier accepts the motor speed information from the motor bridge and provides output voltage level proportional to the motor speed. The Error Amplifiers, one and two, compare voltage levels from the reference and back EMF Amplifiers and provides output voltage levels proportionate to the difference between them. The Switch Select compares voltage levels from Error Amplifiers one and two and determines which Error Amplifier is on and sets the appropriate two stage transistor switch to the On position. Only one switch is on according to the comparison. The Driver Amplifiers one and two are two stage transistor amplifiers series regulator drivers which are driven by the Error Amplifiers. The output of these amplifiers drive the motor. The switches provide the complete path to ground.

3-2-10 WRITE CIRCUITRY

The Write Enable Section accepts the READ/WRITE Control signal from the Drive Select Logic (IC17, pin 13). If the READ/WRITE Control signal is low, drive is provided at the base of Q1 to drive it into conduction and write current is provided at the head center tap from the emitter of Q1. Collector voltage is provided through the normally open contact of the Write Protect switch; therefore, head current can flow only if the cartridge slide switch is in the record position, regardless of the status of the READ/WRITE control input.

The Write Enable section also inverts the READ/WRITE Control input (IC16, pin 12) and uses this signal to enable

the READ DATA output (IC13, pin 6) only if the READ/ WRITE Control input is high.

The Write Head Driver section consists of two "AND" gates, which are enabled if the write mode is selected.

One gate is provided with the WRITE DATA and the other with WRITE DATA. The output of those two gates (IC11, pin 11, IC11, pin 3) are then routed to the open collector drivers (IC17, pin 9 and pin 11) which drive the tape head.

3-2-11 READ CIRCUITRY

The Read Amplifier section accepts the low level read data from the tape head and amplifies this signal to a nominal 2.0 V P-P level (IC18, pin 6).

This amplified data is then clipped at a 28 percent level by the threshold detector (IC19, pin 14) to remove any background noise from the signal.

The peak detector senses peaks in the amplified signal and produces a TTL compatible reproduction of the data (IC19, pin 1).

**Table 3-1. Connector Pin Assignments
Servo Electronics and READ/WRITE
Amplifier PC Assembly
C01 Connector**

SIGNAL	ABBREVIATION USED ON SCHEMATIC	PIN
Beginning of Tape	BOT	1
Ready	RDY	3
Read Data	RD	5
Run	Run	7
Stop	STP	9
Read/Write Control	RWC	11
Write Data	WD	13
Forward/Reverse	F/R	15
Reset	RST	17
Enable Drive 0	EN0	19
Enable Drive 1	EN1	21
Enable Drive 2	EN2	23
Enable Drive 3	EN3	25
Ground	GND	2-26

**Table 3-2. Connector Pin Assignments
Servo Electronics and READ/WRITE
Amplifier PC Assembly
J1A J1B Photocell Connector**

SIGNAL	ABBREVIATION USED ON SCHEMATIC	PIN
Photocell 2	PC2	2
Photocell 1	PC1	4
Cartridge IN	CIN	3
File Protect	FP	5
Ground	GND	1
+12V Endsense	+12V	9
Key	Key	7
+5V	+5V	6
Write Protect	WP	10
Cartridge	COT	8

**Table 3-3. Connector Pin Assignments
Servo Electronics and READ/WRITE
Amplifier PC Assembly
J2 Head Connector**

SIGNAL	ABBREVIATION USED ON SCHEMATIC	PIN
Center Tap	CT	3
Head	HD	5
Head	HD	1
Shield	SHLD	4
Key	Key	2

**Table 3-4. Connector Pin Assignments
Servo Electronics and READ/WRITE
Amplifier PC Assembly
J3 Display Connector**

SIGNAL	ABBREVIATION USED ON SCHEMATIC	PIN
Select	Select	1
+5 VDC	+5 VDC	2
File Protect	File Protect	3
Ground	GND	4
Ready	Ready	5

Table 3-5. Connector Pin Assignments
Servo Electronics and R/W Amplifier PC Assembly
J4A J4B Test Point Connector

SIGNAL	ABBREVIATION USED ON SCHEMATIC	PIN
Ground	TP1	1
Reference Amp Output	TP2	2
Read Amp Output	TP3	3
Back EMF Amp Output	TP4	4
Fwd Driver Amp Output	TP5	5
Rev. Driver Amp Output	TP6	6
Motor Bridge Output	TP7	7
Motor Bridge Output	TP8	8

Table 3-6. Connector Pin Assignments
Servo Electronics and R/W Amplifier PC Assembly
J5 Motor Connector

SIGNAL	ABBREVIATION USED ON SCHEMATIC	PIN
Motor	MTR	4
Motor	MTR	5
Shield	SHLD	2
Sensing Coil	SENS	3
Key	Key	1

3-2-12 MAINTENANCE

See Figure 3-6

3-2-12-1 Motor Control Alignment Procedure

Motor Balance Adjustment

- Connect Motor cable to motor and motion control PC Board connector (J5).
- The following test fixture should be constructed to properly balance the Servo Bridge.

- The motor must be locked while balancing the Servo Bridge. This may be accomplished by inserting a cartridge into the deck.
- With the test fixture applied to test points adjust R71 balance pot to obtain zero volts on the VTVM read-out (± 0.5 mv should be easily achieved). Rotate the motor shaft to insure balance is not at high resistance point.

*Either of two types of Drive motors may be used on this drive. Measure the dc resistance of the motor to determine the correct parallel resistor. Measure between TP6 and TP7. For Motors having 3.6 ohms dc resistance use 120 ohms 1/4w resistor. For Motors having 2.4 ohms dc resistance use a 80 ohm resistor to achieve proper balance.

The Servo Null Pot (R69) and the Motor Speed Adjust Pot (R70) will require adjusting whenever components are changed in the Reference or Back EMF Amplifiers. Whenever these adjustments are made, they should be made *after* the motor balance adjustment has been made.

Reference Amplifier Null Adjust

- Connect a VTVM or digital voltmeter between test points TP2 and TP4, at J4 on the motion control board.
- Adjust R69 for zero volts (± 5 mv) while the servo system is operational. Whenever the Null R69 is adjusted, the speed adjustment should be checked.

The speed of the motor may be measured by using a 1600 frpi calibration test tape and a counter. Adjust R70 to give 24 kHz at pin 5 on the CO1 connector. Another method is to use a stop watch to time the length of the READY status output, while running a cartridge from BOT to EOT. 56 seconds is the proper time interval.

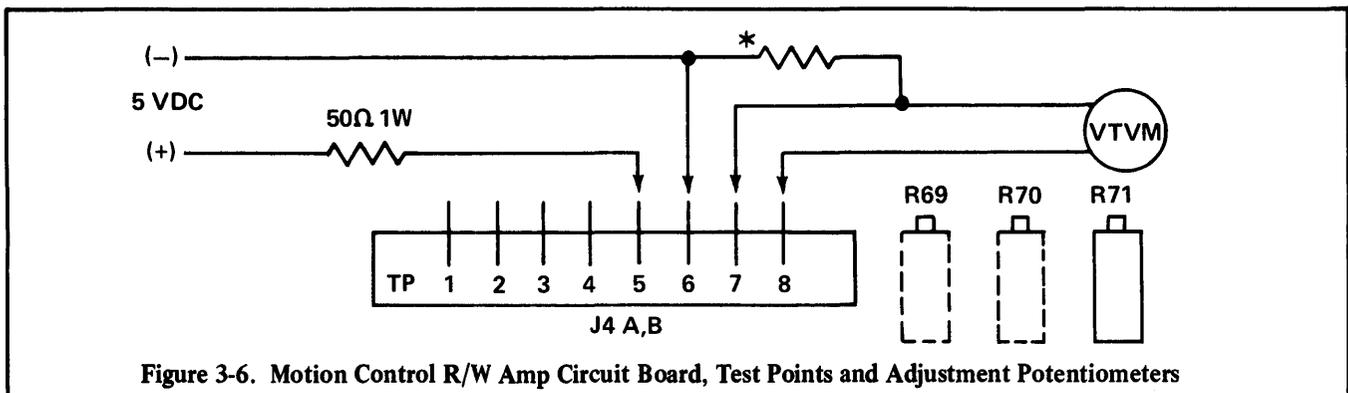


Figure 3-6. Motion Control R/W Amp Circuit Board, Test Points and Adjustment Potentiometers

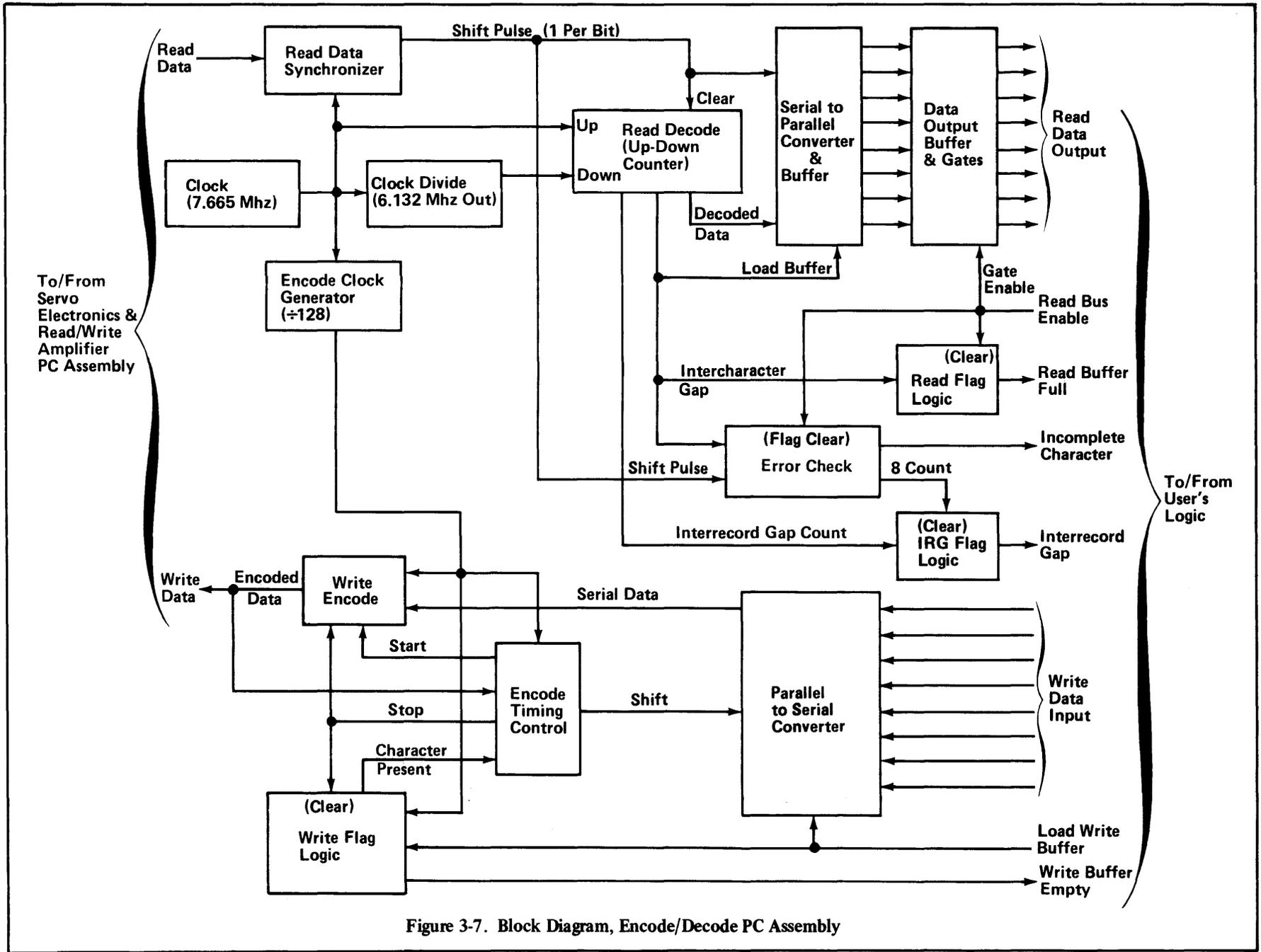


Figure 3-7. Block Diagram, Encode/Decode PC Assembly

**Table 3-7. Interface Pin Assignments
C02 on Encode/Decode PC Assembly**

FUNCTION	SYMBOL USED ON SCHEMATIC	PIN
Data 0	DATA 0	36
Data 1	DATA 1	38
Data 2	DATA 2	44
Data 3	DATA 3	46
Data 4	DATA 4	42
Data 5	DATA 5	40
Data 6	DATA 6	50
Data 7	DATA 7	48
Read Bus Enable	RDBEN	18
Interrecord Gap	IRG	24
Write Buffer Enable	WBE	22
Load Write Buffer	LWRTE	4
Read Buffer Full	RBF	28
Incomplete Character	ICC	26
Ready	RDY	20
Beginning of Tape	BOT	30
Reset	RST	14
Forward/Reverse	F/R	12
Run	RUN	2
Stop	STP	16
Read Write Control	RWC	10
Select 0	SEL-0	6
Select 1	SEL-1	8

3-3 ENCODE/DECODE PC ASSEMBLY

3-3-1 DESCRIPTION

See Figure 3-7

The Encode/Decode PC Assembly provides a serial byte oriented (eight bit parallel) data interface for the user. During write operations the assembly accepts bytes to be written and converts these bytes to a serial bit stream in Variable Cell Width format (described in paragraph 3-3-2) for use by the Read/Write Amplifier PC Assembly.

During read operations, the assembly accepts data from the Read/Write Amplifier PC Assembly in a TTL compatible, Variable Cell Width format and decodes this information into an eight bit byte (high for a "Zero", low for a "One") for output to the user.

Further, the assembly contains an Interrecord Gap Detector and Error Detector with associated output flags.

Also, the assembly contains a Select Decode function which allows one Encode/Decode Assembly to operate with up to

four Read/Write Amplifier Assemblies. The assembly also contains 220/330 ohm input line terminators and line drivers for all user input/output signals. See Figure 2-6.

3-3-2 VARIABLE CELL WIDTH RECORDING

Variable cell width recording derives its name from the fact that a given bit cell varies in width according to whether a "1" or a "0" is being recorded. As shown in Figure 3-8, a bit cell consists of two pulses, a timing pulse of length t followed by a data pulse of length t if the bit is a "0" or length $2t$ if the bit is a "1".

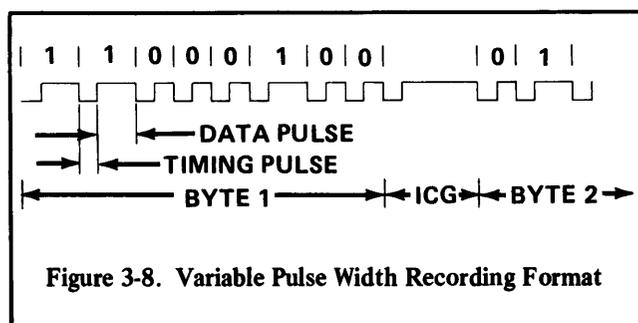


Figure 3-8. Variable Pulse Width Recording Format

When writing data, the length of the timing and data pulses is derived from a crystal oscillator. Implementation of the read decode function is as follows:

1. When the first transition of the timing pulse occurs, a counter is cleared and begins counting in a positive direction at frequency f (7.665 mHz).
2. At the next transition, which ends the timing pulse, the counter begins counting in a negative direction at frequency $0.8f$ (6.132 mHz).
3. At the final transition of the bit cell, the counter contents are sampled. Since counting in the negative direction is accomplished at a lower frequency when counting up, the counter will contain a positive number if the recorded bit was a "0" and a negative number if the recorded bit was a "1".

This encode/decode technique can tolerate a total speed variation of $\pm 20\%$ in the drive mechanism without causing subsequent read errors or impairing the ability to interchange data between drives.

As shown in Figure 3-8, each stream of recorded data ends with a timing pulse so that this encode/decode technique may permit read reverse operation. Although read reverse is

not implemented in the DCD-1, the presence of this final pulse permits a form of error checking. During write operation, the DCD-1 generates an intercharacter gap after each 8 bits; this gap has a length 4 times that of a timing pulse. During read operations, the counter contents are monitored and when the negative count indicates a data pulse of at least 2-1/2 times the length of the timing pulse, an intercharacter gap is indicated. At this point the number of decoded bits in the output register is sensed. If less than 8 bits are present the incomplete character flag is set to indicate the presence of a read error to the user. Reading may continue, however, as the decode function is resynchronized after each intercharacter gap. If the negative count indicates a data pulse of at least 6-1/4 times the length of a timing pulse, the interrecord gap flag is set.

**Table 3-8. Connector Pin Assignments
Encode/Decode PC Assembly**

C01 SIGNAL	SYMBOL USED ON SCHEMATIC	PIN
Write Data	WD	13
Read Data	RD	5
Ready	RDY	3
Reset	RST	17
Forward/Reverse	F/R	15
Run	RUN	7
Stop	STP	9
Read Write Control	RWC	11
Encode 0	EN0	19
Encode 1	EN1	21
Encode 2	EN2	23
Encode 3	EN3	25
Ground	GND	2-26

**Table 3-9. Power Connector Pin Assignments
Encode/Decode PC Assembly**

J1 SIGNAL	SYMBOL USED ON SCHEMATIC	PIN
+5 VDC	+5 VDC	3
Ground	GND	2 & 4

The maximum packing density used by the DCD-1 is 2000 frpi (a byte consisting of 8 "0's"); however, because of the nature of variable cell width recording, further discussion of cartridge capacity and drive data transfer rate is required. The following tables show these characteristics as a function of recorded data.

**Table 3-10. Cartridge Capacity as a Function of Data
(256 Bytes/Block, 1 Inch IRG)**

DATA	CAPACITY
All Zeroes	116,480 Bytes
All Ones	91,136 Bytes
50% Zeroes, 50% Ones	102,400 Bytes

**Table 3-11. Drive Transfer Rate as a Function of Data
(30 ips Tape Speed)**

DATA	TRANSFER RATE
All Zeroes	2857 Bytes/Sec.
All Ones	2069 Bytes/Sec.
50% Zeroes, 50% Ones	2400 Bytes/Sec.

3-3-3 OPERATION (Refer to Fold Out Schematic, Figure 4-7)

The encode/decode PC assembly operates as described below. A write operations timing diagram (Figure 3-9) and a read operations timing diagram (Figure 3-10) are included to aid the reader.

3-3-3-1 WRITE ENCODE

1. When the WRITE BUFFER EMPTY output flag is low the user places an 8 bit byte (high for a "Zero" bit, low for a "One") on the input and applies a low going pulse on the LOAD WRITE BUFFER input (IC24, pin 3).
2. This pulse is inverted (IC24, pin 4) and is used to strobe the input byte into a buffer register (IC36). The same pulse is inverted again and used as an input to (IC16) the write buffer empty set reset latch, causing the output pin 3 to go low. This low level causes the WRITE BUFFER EMPTY output (IC37, pin 11) to go high and applies a low level to the J input of flip flop IC3.
3. On the next clock transition, the Q and \bar{Q} outputs of the flip flop (IC3, pins 3 and 2, respectively), change state. The resultant low level on pin 3 is used (IC37, pin 12) to insure that the WRITE BUFFER EMPTY output remains high. The resultant high level on \bar{Q} (IC3, pin 2) is used as a gate enable at IC16, pin 4.

IC29, PIN 8 (ENCODE CLOCK)

WBE (IC37, PIN 11)

LOAD WRITE BUFFER (IC24, PIN 3)

IC3, PIN 1 (CHARACTER PRESENT)

IC3, PIN 3 (CHARACTER PRESENT SYNCHRONIZED)

IC3, PIN 2

IC14, PIN 2

IC14, PIN 6

IC16, PIN 6 (LOAD PULSE)

IC26, PIN 7 (SERIAL DATA)

IC28, PIN 6 (START ENCODING)

IC2, PIN 1

IC2, PIN 3 (ENCODING DATA)

IC2, PIN 2

IC2, PIN 8

IC2, PIN 6

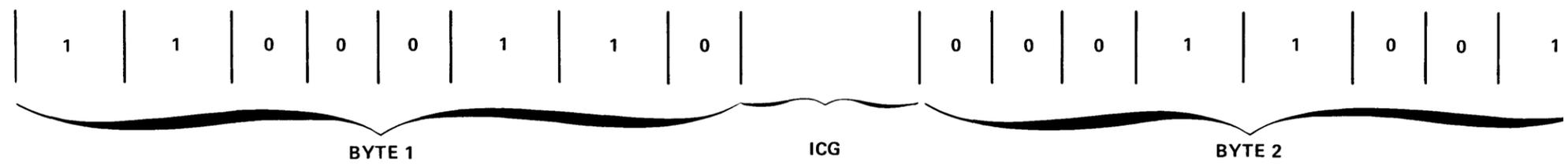
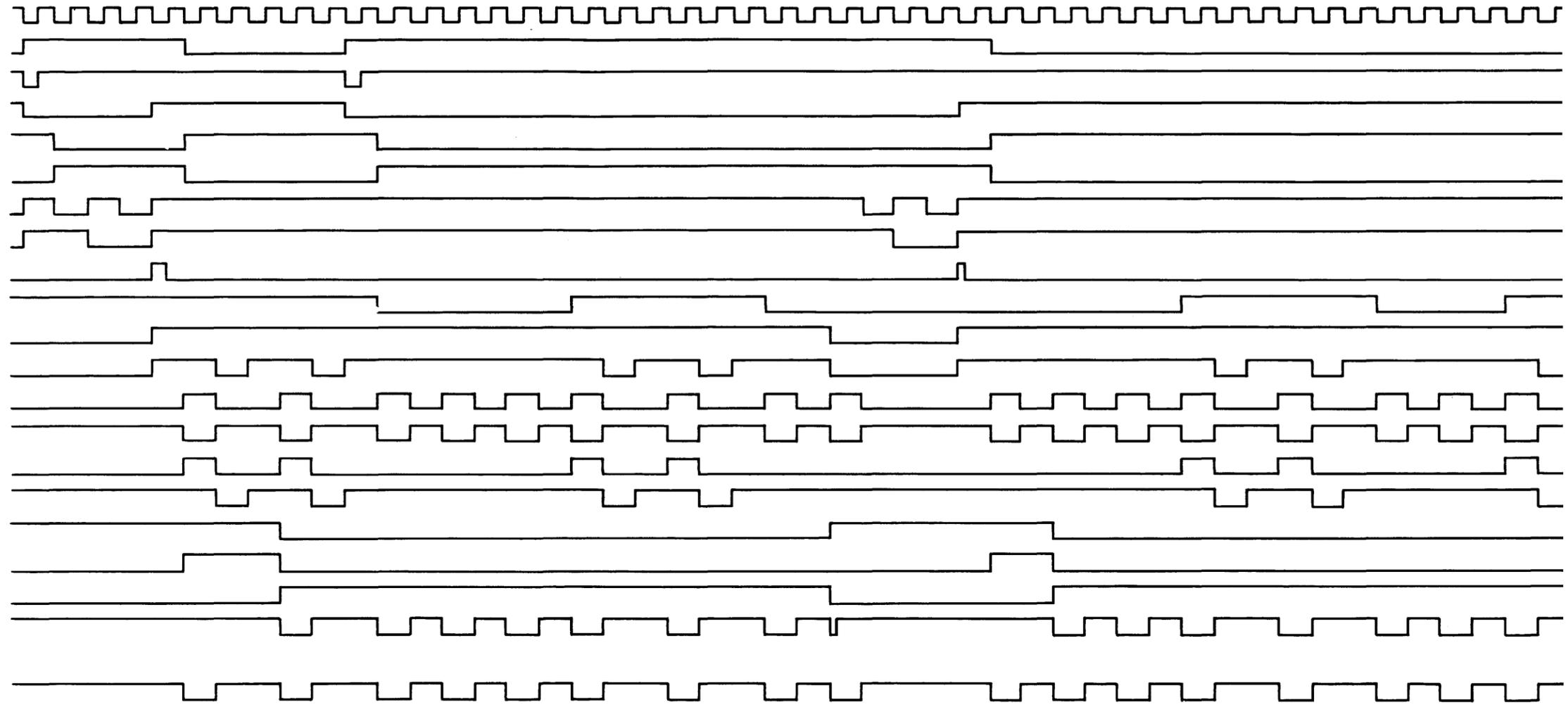
IC1, PIN 1 & 4

IC1, PIN 8 & 11

IC1, PIN 5

IC16, PIN 8

IC8, PIN 10 (WRITE DATA)



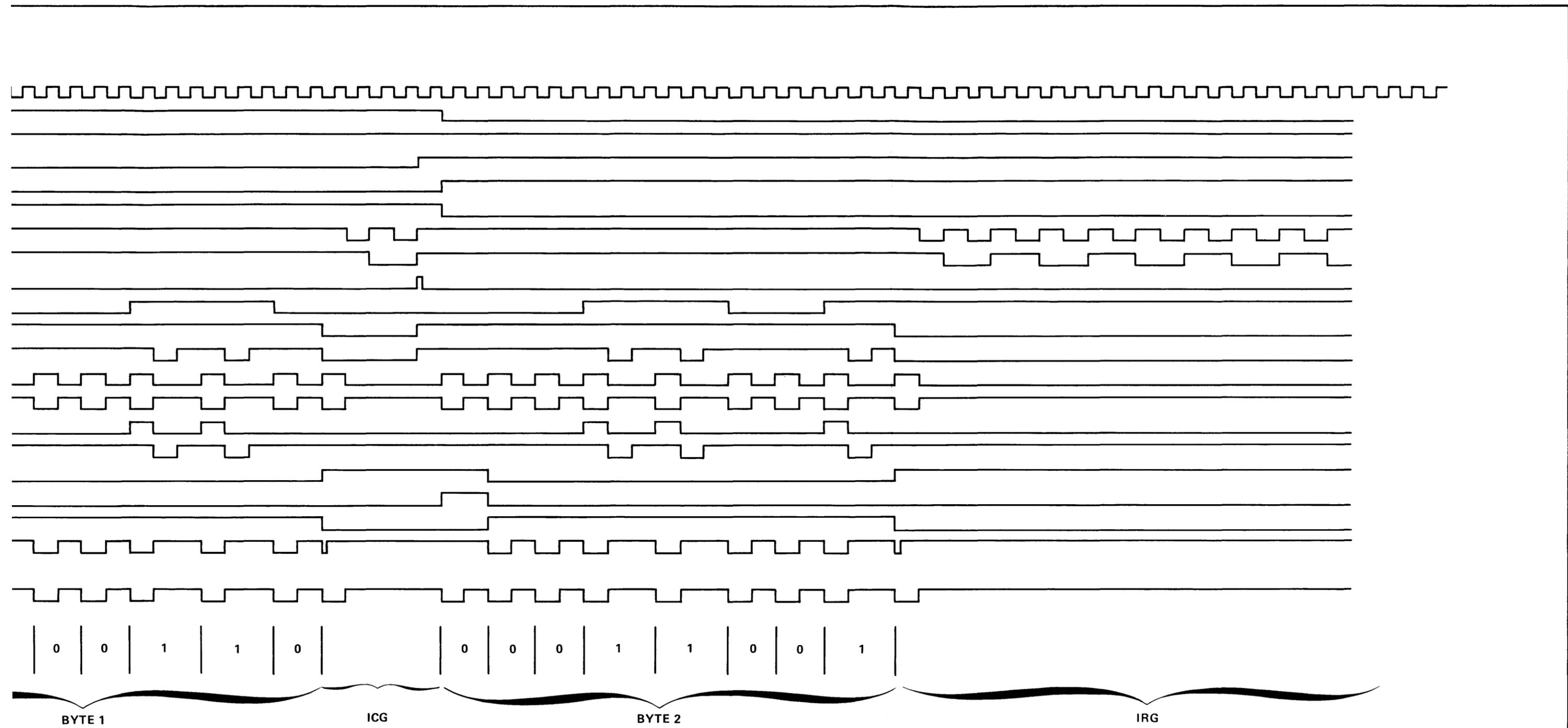
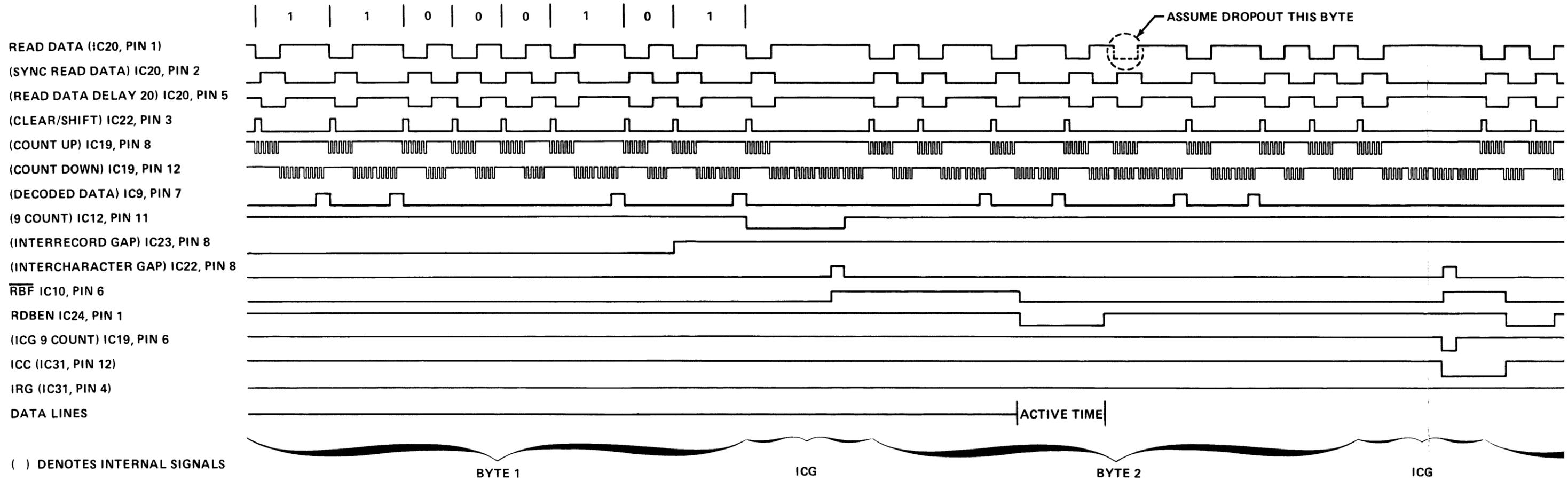


Figure 3-9. Write Operation Encode Timing Diagram



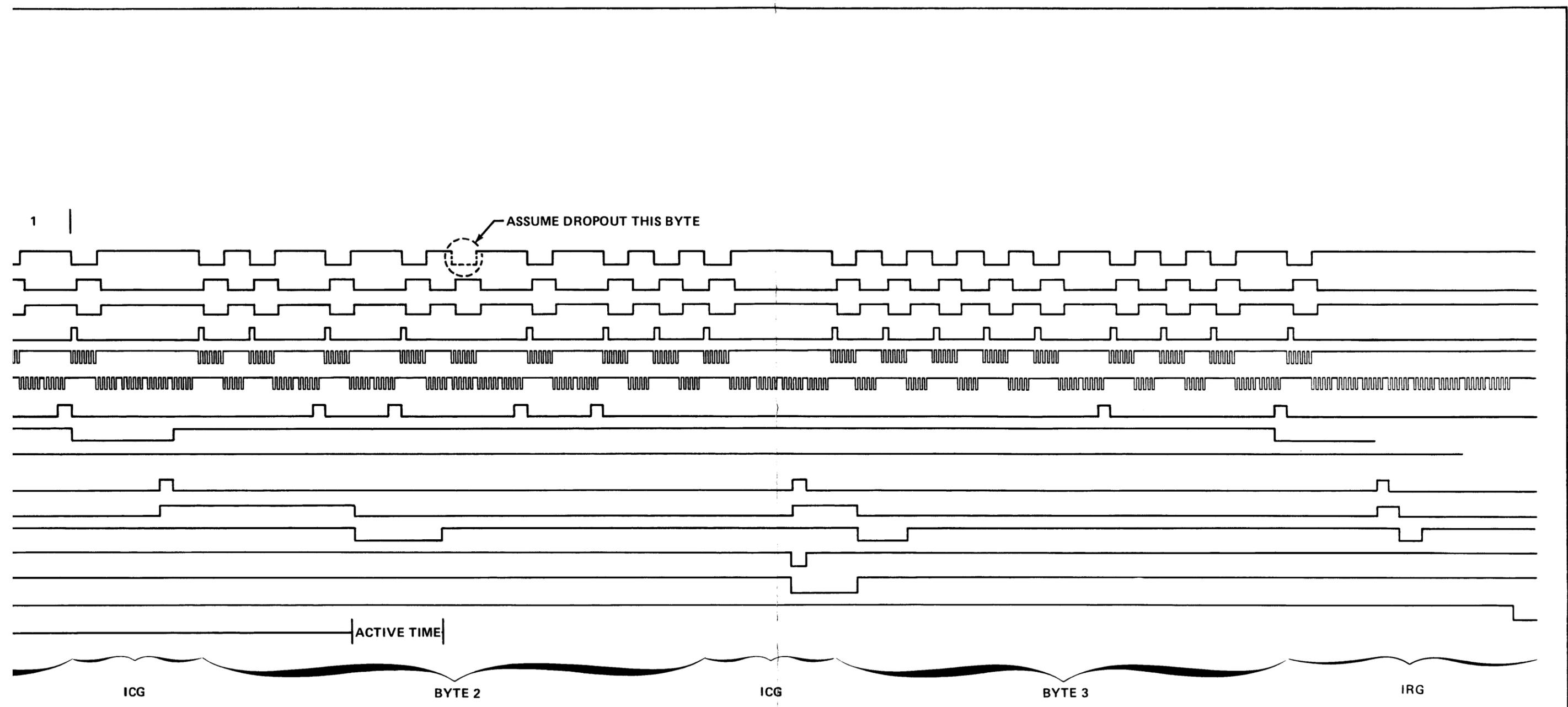


Figure 3-10. Read Operation Timing Diagram

4. Up to this point, IC14 has been a free running counter whose output was used to generate a short duration pulse at IC15, pin 6 every four clock periods. When IC3, pin 2 goes high, this pulse is gated through IC16 giving pin 6 a short duration low going pulse. This pulse clears IC27 and QD (IC27, pin 11) goes low, disabling the free running counter (IC14). The pulse at IC16, pin 6 is also used as a latch reset for IC16, pin 2 and as the load input enable for the parallel to serial shift register (IC26). The input data in the buffer (IC36) is thus loaded into the shift register (IC26). One clock period after the pulse occurs at IC16, pin 6, IC3, pin 3 goes high and the WRITE BUFFER EMPTY output is enabled at IC37, pin 13.
5. When IC27 is cleared, its low output at pin 11 is inverted at IC28, pin 6. This high level is used as a gate enable at IC15, pin 2 and at IC17, pin 1 to start the encode function.
6. When the encode circuit is enabled, IC2, pin 3 is low and IC2, pin 6 is high. This latter signal is fed back to IC2, pin 1 via an AND gate (IC15, pin 11). One clock period later, the flip flop output (IC2, pin 3) changes state to the high level. If a "Zero" is to be written, IC26, pin 7 will be low. This level is inputted to IC17, pin 13. The resultant high output is inverted at (IC28, pin 8) and the J input to the JK flip flop (IC2, pin 8) is held low and IC2, pin 6 remains high. The resultant high input to IC2, pin 3 causes IC2, pin 3 to change state once each clock period. This signal is inverted (IC28, pin 10) to form the Variable Cell Width Recording pattern for a "Zero" as described in Paragraph 3-3-2.

If a "One" is to be recorded IC26, pin 7 will be high and the state of IC2, pin 8 will correspond to the level output at IC2, pin 3. In this instance, when IC2, pin 3 goes high, IC2, pin 8 also goes high. This causes IC2, pin 6 to switch low after one clock period. Because during the first clock period (starting from IC26, pin 7 switching high) IC2, pin 6 (and consequently IC2, pin 1) is high, IC2, pin 3 also switches low at the end of the first clock period according to the rules of operation for a J-K flip flop.

This low level is applied to IC2, pin 8 and consequently IC2, pin 6 returns high at the end of the second clock period. Since IC2, pin 1 is low during second clock period, IC2, pin 3 does not switch at the end of the clock period 2 but remains low. The high input at IC2, pin 1 during clock period 3 causes IC2, pin 3 to switch low at the end of the third period. The signal at IC2, pin 3 is inverted at IC28, pin 10 to form the variable Cell Width Recording pattern

for a "One" as described in Paragraph 3-3-2. This signal is low for one clock period then switches high for 2 clock periods before switching low again.

7. The compliment of the signal at IC2, pin 3 (IC2, pin 2) is routed to a shift enable circuit consisting of IC1 (Dual J-K flip flop) and NAND gate IC16 (pin 8). At the second low going transition on IC2, pin 2 (which occurs at the end of the first data bit) IC1, pin 5 goes high to enable the NAND gate at pin 10, IC16. The low level occurring at IC1, pin 6 is fed back to IC1, pins 1 and 4 to prevent further flip flop operation as a result of changes in logic state at IC2, pin 2. Thereafter, each time IC2, pin 3 goes high, a low level occurs at IC16, pin 8. The low going excursions occurring at IC16, pin 8 are used to step the 8 bit counter, IC27, and to shift excessive bits out of the parallel to serial shift register (IC26).
8. After eight low going transitions (IC16, pin 8) the counter output (IC27, pin 11) goes high. This high level allows the counter comprised of the dual JK flip flop, IC14, to count at the clock rate. Every four clock periods IC14, pin 6 switches high and a high going pulse is produced at IC15, pin 6. If during writing of a given byte, a second byte is entered into buffer register IC36, IC15, pin 4 will have been set high and the pulse at IC15, pin 6 will be gated through to IC16, pin 6. The low pulse at IC16, pin 6 causes operation to begin on the second input byte, commencing at step 4 above. The four clock period delay generates the required intercharacter gap between successive bytes. If another byte had not been entered during writing of the previous byte, IC16, pin 4 will remain low, no further operation will be initiated and the WRITE DATA output to the Read/Write Amplifier PC Assembly will remain at the high logic state as required during an interrecord gap.

3-3-3-2 READ OPERATIONS

1. The READ DATA input from the read amplifier is applied to the read data Synchronizer (IC20, pin 1). Its compliment is applied to IC20, pin 4. The synchronizer circuit generates a positive going pulse (IC22, pin 3) for each low going transition on the READ DATA input line. This circuit further interlocks transitions of the READ DATA input to the output of the crystal clock so that subsequent read decode functions occur in proper timing sequence.
2. The high going pulse at IC22, pin 3 clears the read decode counters (IC's 7, 8, and 9 (all outputs go

low)); it pulses the shift input of serial to parallel converter (IC25, pin 8); and the low going trailing edge of the pulse steps the 9 bit counter (IC13, pin 14) of the Error Check Logic circuit.

3. When the first low going transition on the READ DATA input is shifted through the synchronizer, IC20, pin 2 goes high and the 7.665 MHz clock is enabled at IC18, pin 8. This clock output, when enabled, is applied to the count up input of the up-down counters of the read decode circuit. The counters then count up at the clock frequency until the READ DATA input returns high.
4. When READ DATA returns high, IC20, pin 3 goes high and the output of the clock divide circuit (IC15, pin 8) is enabled (IC19, pin 12). The clock divide circuit creates a low level (IC17, pin 8) every fifth period of the clock. This low level is applied to IC15, pin 10 to prevent every fifth clock pulse from appearing at IC15, pin 8. The net result is that the clock used at the count down input of the up-down counters contains, per unit time, 0.8 the number of clock transitions as the count up clock input.
5. During the timing pulse of a data bit, as described in Paragraph 3-3-2, the up-down counters (IC's 7, 8, and 9) will be counting up at the clock frequency. When the READ DATA input returns high at the end of the timing pulse, the counters will begin to count down at a rate which is 0.8 that of count up operation. At the end of the data pulse, when READ DATA switches low, counter output (IC9, pin 7) is inverted and strobed into the serial to parallel register (IC25, pins 1 and 2) by the pulse generated at IC22, pin 3. This pulse also resets the counters.

If the input bit to be decoded was a "Zero" the timing pulse and data pulse would be of the same length as described in Paragraph 3-3-2. In this instance, the contents of the counters would be positive at the end of the data pulse and IC9, pin 7 would be at a low logic level. If the input bit was a "One", the data pulse would be twice as long as the timing pulse; at the end of the data pulse, the counter would contain a negative number and IC9, pin 7 would output a high level.

6. When the ninth high going pulse occurs at IC22, pin 3, both the 2^0 and 2^3 output bits of counter IC13 in the error check circuit go high. The high level at the 2^3 output (pin 11) resets the interrecord gap latch and IC23, pin 8 goes high. This high level enables gates at the inputs to the latches for the READ BUFFER FULL and INCOMPLETE CHARACTER flags.

Since these latches are not enabled until the first full byte is read, immunity to interrecord noise is provided and precludes noise from appearing as data on the Read Data bus.

7. The ninth pulse at IC22, pin 3 occurs at the start of the intercharacter gap, a timing pulse followed by a data pulse which is 4 times the length of the timing pulse. When IC's 7, 8 and 9 reach a count of -128 (all counter outputs are high except for a low on IC8, pin 7) a low level appears at NAND gate IC21, pin 8 which in turn, creates a high level at IC22, pin 8. This high level causes buffer register (IC33) to be loaded with the contents of serial to parallel shift register. It also sets the read flag latch causing IC10, pin 6 to go high; this level is inverted to form the low going READ BUFFER FULL output.

If the counter (IC13) had not reached a count of 9 (eight bits were not present in the byte) when the intercharacter gap is sensed IC22, pin 8 goes high (as assumed in byte 2 of Figure 3-4), a low level is generated at IC19, pin 6. This low level sets the error flag SET/RESET latch and IC10, pin 8 goes high. This level is inverted at IC31, pin 12 to form the INCOMPLETE CHARACTER output flag. Sensing the intercharacter gap (high level at IC22, pin 8) also causes a high going pulse to occur at IC12, pin 6. This pulse clears the 9 bit counter (IC13) of the error circuit.

8. If the timing pulse in 7 above is at the end of a record, the counters, IC's 7, 8 and 9 will continue in a negative direction. When a count of -512 occurs (all counter outputs are high except for a low on IC9, pin 2), a low level occurs on IC23, pin 3 which sets the interrecord gap latch and IC23, pin 6 goes high. This level is inverted at IC31, pin 4 to form the low going INTERRECORD GAP, output. The low output at IC23, pin 3 also disables the clock inputs to the up down counters at IC19, pin 2 and at IC19, pin 9.
9. After the READ BUFFER FULL output goes low, the user must apply a low going pulse of at least 50 nanoseconds duration to the READ BUS ENABLE input. This pulse enables the tri-state data output gates (IC's 32 and 34) and resets the read flag and error flag latches.

3-3-4 INTERRECORD GAP TIME CONSIDERATIONS

To insure the writing of proper length interrecord gaps, the following delays should be used.

1. After commanding forward tape movement, delay 27 milliseconds before entering the first data byte.

2. After writing (or reading) the last data byte, delay 5 milliseconds before commanding a stop.

3-3-5 WRITE FLAG TIMING

When writing data, the following timing restrictions must be considered:

1. When the first byte of data is strobed in, WRITE BUFFER EMPTY will go low again within from 16.67 microseconds to 83.5 microseconds, depending on internal logic timing.
2. The LOAD WRITE BUFFER input must be a pulse of at least 50 nanoseconds but no greater than 1.5 microseconds. The LOAD WRITE BUFFER input must occur no sooner than 4 microseconds but prior

to 340 microseconds after WRITE BUFFER EMPTY goes low.

3-3-6 READ FLAG TIMING

When reading data, the following timing restrictions must be considered:

1. After the first byte is decoded, subsequent bytes will occur on the average, every 350 microseconds.
2. The READ BUS ENABLE input must be held true for at least 50 nanoseconds for valid data to appear on the data bus. This input must occur no sooner than 20 nanoseconds after READ BUFFER FULL goes low. READ BUS ENABLE should return high within 200 microseconds of READ BUFFER FULL going low.

SECTION IV. PARTS LISTS, SCHEMATICS, AND PC BOARD LAYOUTS

Parts List, DCD-1 Mechanism Assembly			
INDEX NUMBER	PART NUMBER	DESCRIPTION	QTY.
1	81-1530-9670-6	Ejector Slide	1
2	81-0930-9770-7	Spiral Pin – 3/32 DIA x 3/16 L	1
3	83-9260-4501-0	Screw – Mach., Pan Hd., 2-56 x 3/16	2
4	83-9261-4201-5	Washer – Lock, Flat, Int. Tooth, #2	1
5	83-9260-2001-3	Nut – Hex, Plain 2-56 x .188 WD	1
6	83-9261-2132-4	Screw – Cap, Skt. Hd., 4-40 x 5/16	1
7	83-9260-4507-7	Screw – Mach., Pan Hd., 2-56 x .625	1
8	81-2716-1860-5	Head – Single Track R/W	1
9	81-1630-9870-0	Head Insulating Tape	1
10	83-0003-0970-4	Cable Assy. Head	1
11	81-0934-3480-1	Ball – Azimuth Adjust	2
12	81-1432-6660-9	Screw 6-32 x 5/16 Pan Head	5
13	83-0003-0993-6	Mechanism Base Assy.	1
14	81-1330-9880-6	Spring – Eject Release Slide	1
15	83-7270-0878-7	Ring – Retng., Ext., .113 Free Dia.	13
16	81-0150-0008-6	Eject Button Assy.	1
17	81-0930-9540-4	Ring – Retaining, Reinforced E	2
18	83-9261-0071-6	Setscrew – Cup Pt., 8-32 x 3/8	2
19	81-1330-9720-4	Motor Spring	1
20	81-1332-1000-5	Spring – Azimuth	1
21	81-0934-4680-5	Nut – Stop, 2-56	1
22	81-0430-9620-5	Whiffle Tree Shaft	1
23	81-0430-9790-6	Roller – Detent Lock Arm	1
24	81-0330-9440-0	Release Rocker Arm	1
25	83-0003-0985-2	Detent Lock Arm Assy.	1
26	83-9261-2003-7	Screw – Cap, Skt. Hd., 4-40 x 1/2	1
27	81-1317-7120-6	Spring Bank Item	1
28	81-0430-9750-0	Shaft – Right Lock Arm	1
29	83-7270-0876-1	Ring – Retng., Ext., .072 Free Dia.	4
30	81-0430-9780-7	Shaft – Detent Lock Arm	1
31	83-0003-0988-6	Rear Lock Arm Assy.	1
32	81-0430-9570-2	Roller	2
33	83-0003-0987-8	Right Lock Arm Assy.	1
34	81-1330-9930-9	Spring – Rear Lock Arm	1
35	83-0003-0984-5	Right Lock Cross Bar Assy.	1
36	81-0330-9830-2	Link Right Lock Arm	1
37	83-0003-0969-6	Cable Assy. Motor	1
38	81-0330-9480-6	Bottom Cover	1
39	83-0003-0994-4	Motor Assy.	1
40	81-0430-9550-4	Motor Pivot Shaft	2
41	81-0334-3350-9	Retainer – Motor Pivot	2
42	83-0003-0990-2	Transfer Bracket Assy.	1
43	83-0003-0989-4	Transfer Pivot Bkt. Assy.	1
44	81-1330-9900-2	Return Spring – Transfer Bkt.	1
45	83-0003-0986-0	Left Lock Arm Assy.	1
46	81-0430-9760-9	Shaft – Left Lock Arm	1
47	81-0330-9400-4	Link – Lock Arm	1
48	83-0003-0992-8	Right Guide Rail Assy.	1
49	83-9260-2001-3	Nut – Mach. Screw Hex 2-56	2
50	83-0003-0991-0	Left Guide Rail Assy.	1
51	83-9260-4519-2	Screw – Mach., Pan Hd., 4-40 x 5/8	1

Parts List, DCD-1 Mechanism Assembly (Cont.)

INDEX NUMBER	PART NUMBER	DESCRIPTION	QTY.
52	83-9260-4514-3	Screw - Pan Hd., 4-40 x 5/16	2
53	83-9260-4522-6	Screw - Mach., Pan Hd., 4-40 x 1	2
54	81-1530-9640-9	Front Bezel	1
55	83-9630-0085-2	Lug	1
56	81-1434-4820-7	Screw - Pan Hd., 2-56 x 3/4	2
57	83-4930-3905-7	End Sense Assembly (includes item 50)	1
58	81-0884-2440-8	Washer #4 Plastic	1
59	83-1550-6166-2	Switch - Snap Action	2
60	81-2712-7041-5	TSTR - SI NPN Photo Sens FPT100A	2
61	81-2712-1310-0	Lamp - 2.5V Lens End TS1748	1
62	81-0430-9520-7	Washer - Shoulder	1
63	83-0003-1016-5	Head Clamp Assy.	1

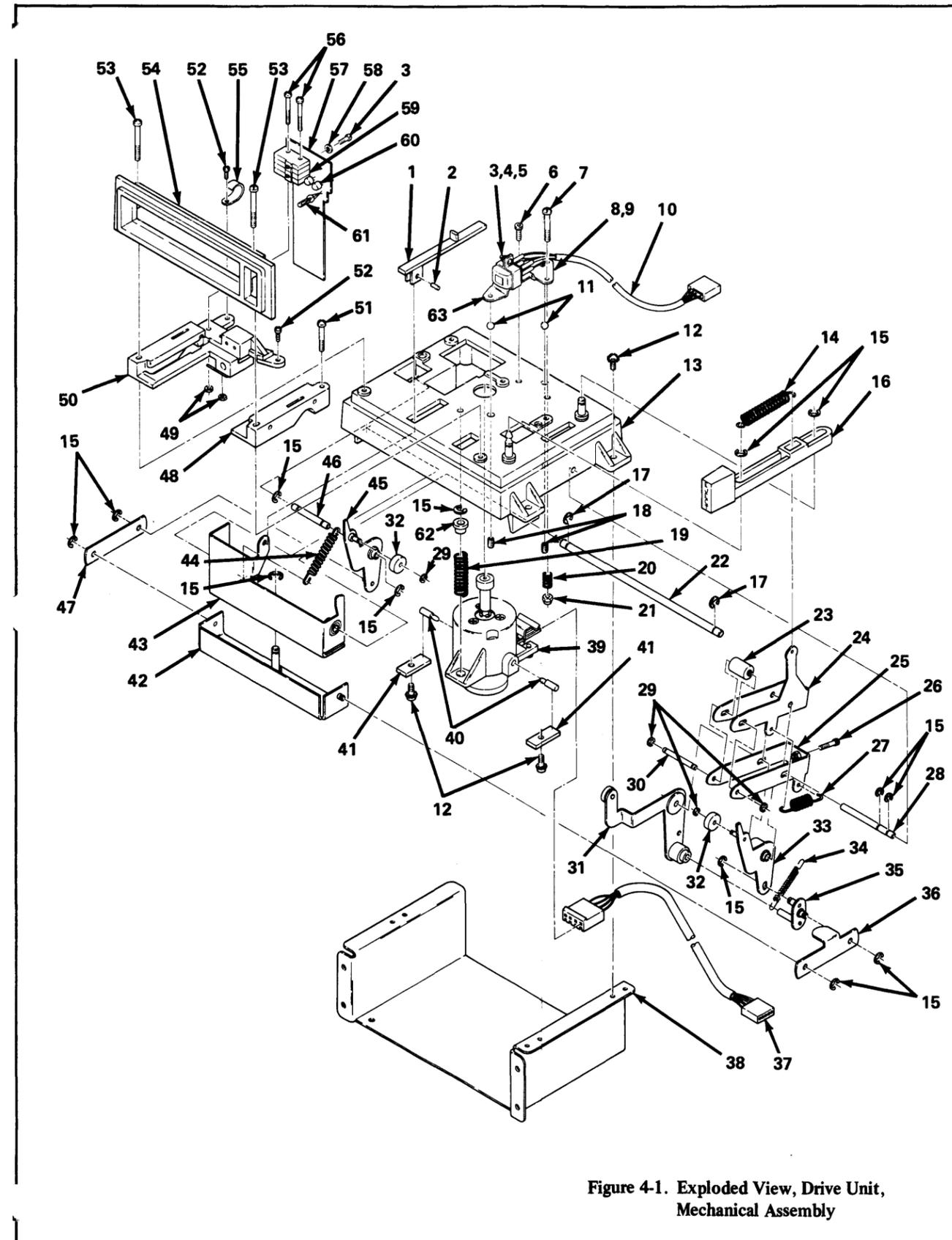


Figure 4-1. Exploded View, Drive Unit, Mechanical Assembly

NOTES

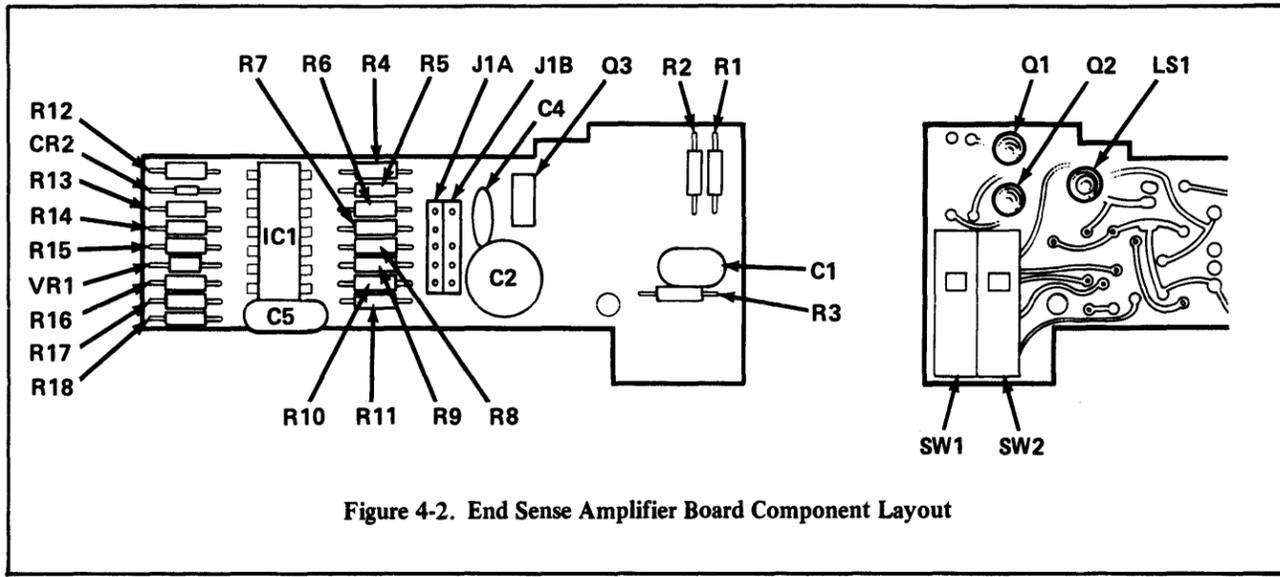


Figure 4-2. End Sense Amplifier Board Component Layout

Parts List, End Sense Amplifier PC Assembly, 83-4930-3905-7, Issue E			
INDEX NUMBER	PART NUMBER	DESCRIPTION	QTY.
C1	83-1510-4648-5	Capacitor - Fixed, Film, 1 UF 100V 10%	1
C3	83-1510-2354-2	Capacitor - Fixed, Elc, 100 UF 16V	1
C4	83-1510-1024-2	Capacitor - Fixed, Ceramic, 1000 PF 1000V 10%	1
C5	83-1510-5120-4	Capacitor - Fixed, Mic, 500 PF 500V 5%	1
C6	81-1510-1075-4	Capacitor - Fixed Ceramic, .01 UF 10V	1
CR2	83-1530-0083-7	Diode - SI Switching 1N914	1
IC1	83-1530-8307-2	IC - Quad Comp LM339N	1
J1A, 1B	83-1610-1912-6	Connector - 5 Contact	2
LS1	81-2712-1310-0	Lamp - 2.5V Lens End TS1 748	1
Q1, Q2	81-2712-7041-5	Transistor - SI, NPN Photo-Sens FPT100A	2
Q3	83-1530-2434-0	Transistor - SI, NPN Power-Darl MJE800	1
R1, 2	83-9520-2223-0	Resistor - Fixed, Comp, 22M Ohm 1/4W 5%	2
R3, 18	83-9520-2088-7	Resistor - Fixed, Comp, 1K Ohm 1/4W 5%	2
R4, 5	83-9520-2089-5	Resistor - Fixed, Comp, 8.2K Ohm 1/4W 5%	2
R6	83-9520-2167-9	Resistor - Fixed, Comp, 39K Ohm 1/4W 5%	1
R7	83-9520-2132-3	Resistor - Fixed, Comp, 200 Ohm 1/4W 5%	1
R8, 9, 14, 15	83-9520-2112-5	Resistor - Fixed, Comp, 10K Ohm 1/4W 5%	4
R10, 11	83-9520-2195-0	Resistor - Fixed, Comp, 1.3M Ohm 1/4W 5%	1
R12	83-9520-2182-8	Resistor - Fixed, Comp, 300K Ohm 1/4W 5%	1
R13	83-9520-2162-0	Resistor - Fixed, Comp, 20K Ohm 1/4W 5%	1
R16, 17, 18	83-9520-2098-6	Resistor - Fixed, Comp, 2.7K Ohm 1/4W 5%	3
SW1, 2	83-1550-6166-2	Switch - Snap Action	2
VR1	83-1530-0465-6	Diode - SI Zener 6.8V	1
Not shown	83-0003-0991-0	Guide Rail, Left, Assy	1
	83-9260-4501-0	Screw Pan Head 2-56 x 3/16	1
	81-1434-4820-7	Screw Pan Head 2-56 x 3/4	2
	83-9620-2001-3	Nut Mach. Screw Hex 2-56	2
	81-0884-2440-8	Washer #4	1

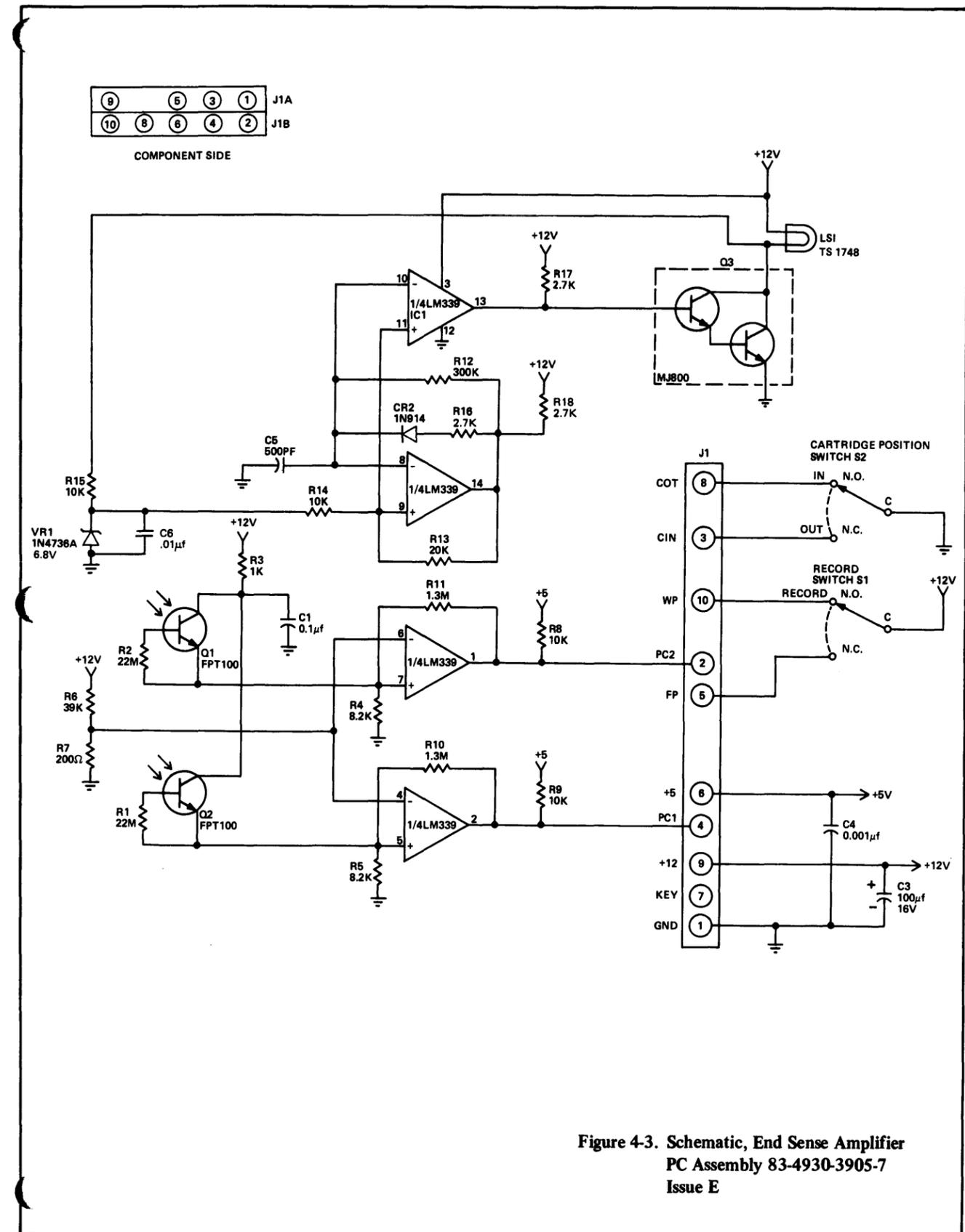


Figure 4-3. Schematic, End Sense Amplifier PC Assembly 83-4930-3905-7 Issue E

Parts List, Servo Electronics and Read/Write Amplifier PC Assembly 83-4930-3904-0, Issue E			
INDEX NUMBER	PART NUMBER	DESCRIPTION	QTY.
C1, 6-10	83-1510-2307-0	Capacitor – Fixed, Ceramic, .05 UF 10V	6
C2	83-1510-6415-7	Capacitor – Fixed, Tan, 2.2UF 35V 10%	1
C3, 28	83-1510-6413-2	Capacitor – Fixed, Tan, 1.0 UF 35V 10%	2
C4, 5, 11	83-1510-1024-2	Capacitor – Fixed, Ceramic, 1000 PF 1000V 10%	3
C12	83-1510-5041-2	Capacitor – Fixed, Mic, 1000 PF 500V 5%	1
C13, 14	83-1510-1187-7	Capacitor – Fixed, Ceramic, .1 UF 50V	2
C15	83-1510-5164-2	Capacitor – Fixed, Mic, 150 PF 500V 5%	1
C16	83-1510-5263-2	Capacitor – Fixed, Mic, 2 PF 500V	1
C17, 19, 30	83-1510-1075-4	Capacitor – Fixed, Ceramic, .01 UF 50V	3
C18	83-1510-2355-9	Capacitor – Fixed, Elc, 100 UF 16V	1
C20	83-1510-6411-6	Capacitor – Fixed, Tan, .47 UF 35V 10%	1
C21, 22	83-1510-6126-0	Capacitor – Fixed, Tan, .18 UF 35V 10%	2
C23-27	83-1510-4649-3	Capacitor – Fixed, Film, .01 UF 100V 10%	5
C29	83-1510-5028-9	Capacitor – Fixed, Mic, 470 PF 500V 10%	1
CR1	83-1530-0151-2	Diode – Rectifier 1N4004	1
F1	83-7550-8159-9	Fuse – 2 Amp, Microfuse	1
HS1	81-0930-9710-3	Heat Sink	1
IC1	83-1530-8162-1	IC – Dual One Shot SN74123N	1
IC2	83-1530-8163-9	IC – Dual J-K SN74107N	1
IC3	83-1530-8171-2	IC – Shaft Req SN74194N	1
IC4, 6, 16	83-1530-8142-3	IC – Hex Inverter SN7404N	3
IC5, 7	83-1530-8060-7	IC – Quad 2 Input NAND SN7400N	2
IC8, 12	83-1530-8069-8	IC – Dual 4 Input NAND SN7420N	2
IC9, 10	83-1530-8143-1	IC – Tri 3 Input NANDD SN7410N	2
IC11	83-1530-8168-8	IC – Quad 2 Input AND SN7408N	1
IC13, 15	83-1530-8333-8	IC – Quad 2 Input OR SN7432N	2
IC14	83-1530-8356-9	IC – Hex, Tri-State SN74125N	1
IC17, 20	83-1530-8174-6	IC – Hex, Inverter Buf SN7406N	2
IC18	83-1530-8358-5	IC – Op Amp 8 Pin Dip SN72748P	1
IC19	83-1530-8307-2	IC – Quad Comp LM339N	1
IC21	78-8032-2739-2	IC – Quad Op Amp LM324N	1
J1A, 1B	83-1610-1912-6	Connector – 5 Circuit	2
J2, 3, 5, 6	83-1610-1913-4	Connector – 5 Circuit	4
J4A, 4B	83-1610-1914-2	Connector – 4 Circuit	2
J7	83-1610-1915-9	Connector – 3 Circuit	1
J8	83-1610-1916-7	Connector – 6 Circuit	1
J9	81-2817-4620-6	Connector – 2 Circuit	1
P1, 2	83-1610-1907-6	Plug – Jumper	2
Q1	81-2712-5290-0	Transistor – SI, NPN Low Power 2N3416	1
Q2, 3, 6, 7, 8	81-2712-5530-9	Transistor – SI, NPN 7553A	5
Q4, 5	83-1530-2424-1	Transistor – SI, PNP High Power MJE2955	2
Q9, 10	83-1530-2425-8	Transistor – SI, NPN High Power MJE3055	2
Q11	83-1530-2155-1	Transistor – SI, PNP Low Power 2N3638A	1
R1, 3	83-9520-2164-6	Resistor, Fixed, Cmp, 24K Ohm 1/4W 5%	2
R2, 8, 14, 19, 24, 44, 54, 55, 59, 67	83-9520-2088-7	Resistor – Fixed, Cmp, 1K Ohm 1/4W 5%	10
R4	83-9520-2099-4	Resistor – Fixed, Cmp, 82 Ohm 1/4W 5%	1
R5, 86	83-9520-2107-5	Resistor – Fixed, Cmp, 100 Ohm 1/4W 5%	2
R6, 75, 81	83-9520-2132-3	Resistor – Fixed, Cmp, 200 Ohm 1/4W 5%	3
R7	83-1520-7349-6	Resistor – Fixed, Film, 300 Ohm 1/2W 2%	1

Parts List, Servo Electronics and Read/Write Amplifier PC Assembly (Cont.)

INDEX NUMBER	PART NUMBER	DESCRIPTION	QTY.
R9	83-9520-4144-6	Resistor - Fixed, Cmp, 510 Ohm 1W 5%	1
R10	83-1520-7174-8	Resistor - Fixed, Film, 390 Ohm 1/2W 2%	1
R11, 70	83-1520-1574-5	Resistor - Variable, Ceramic, 1K Ohm	2
R12, 13, 18	83-1520-7308-2	Resistor - Fixed, Film, 10K Ohm 1/4W 2%	3
R15	83-1520-7259-7	Resistor - Fixed, Film, 20K Ohm 1/4W 2%	1
R16	83-1520-0356-8	Resistor - Fixed, Film, 150 Ohm 1/4W 2%	1
R17, 23, 29 37, 38	83-9520-2112-5	Resistor - Fixed, Cmp, 10K Ohm 1/4W 5%	5
R20, 21	83-1520-7282-9	Resistor - Fixed, Film, 1K Ohm 1/4W 2%	2
R22, 41-43, 84, 85	83-9520-2096-0	Resistor - Fixed, Cmp, 3.9K Ohm 1/4W 5%	6
R25, 26	83-9520-2152-1	Resistor - Fixed, Cmp, 4.3K Ohm 1/4W 5%	2
R27, 34	83-9520-2095-2	Resistor - Fixed, Cmp, 3.3K Ohm 1/4W 5%	2
R28, 35	83-1520-0500-1	Resistor - Fixed, Film, 499K Ohm 1/4W 1%	2
R30	83-9520-2119-0	Resistor - Fixed, Cmp, 100K Ohm 1/4W 5%	1
R31, 32	83-9520-2162-0	Resistor - Fixed, Cmp, 20K Ohm 1/4W 5%	2
R33	83-9520-2179-4	Resistor - Fixed, Cmp, 180K Ohm 1/4W 5%	1
R36	83-9520-2180-2	Resistor - Fixed, Cmp, 200K Ohm 1/4W 5%	1
R39, 40	83-9520-2172-9	Resistor - Fixed, Cmp, 82K Ohm 1/4W 5%	2
R45, 46, 61, 63, 65, 66	83-1520-0501-9	Resistor - Fixed, Film, 15K Ohm 1/4W 1%	6
R47	83-1520-0502-7	Resistor - Fixed, Film, 68.1K Ohm 1/4W 1%	1
R48, 49	83-1520-0503-5	Resistor - Fixed, Film, 47.5K Ohm 1/4W 1%	2
R50, 53	83-1520-0504-3	Resistor - Fixed, Film, 78.7K Ohm 1/4W 1%	2
R51	83-1520-0505-0	Resistor - Fixed, Film, 57.6K Ohm 1/4W 5%	1
R52	83-1520-0506-8	Resistor - Fixed, Film, 158K Ohm 1/4W 1%	1
R56	83-1520-7220-9	Resistor - Fixed, Film, 220 Ohm 1/2W 2%	1
R57	83-1520-7340-5	Resistor - Fixed, Film, 68 Ohm 1/2W 2%	1
R58	83-1520-0507-6	Resistor - Fixed, Film, 54.9K Ohm 1/4W 1%	1
R60, 62, 64, 68	83-1520-0508-4	Resistor - Fixed, Film, 243K Ohm 1/4W 1%	4
R69	83-1520-1568-7	Resistor - Variable, Ceramic, 20K Ohm	1
R71	83-1520-1573-7	Resistor - Variable, Ceramic, 500 Ohm	1
R72	83-1520-0509-2	Resistor - Fixed, Film, 2.74K Ohm 1/4W 1%	1
R73	83-1520-0510-0	Resistor - Fixed, Film, 221 Ohm 1/4W 1%	1
R74, 79	83-1520-7339-7	Resistor - Fixed, Film, 62 Ohm 1/2W 2%	2
R76, 78	83-1520-7332-2	Resistor - Fixed, Film, 30 Ohm 1/2W 2%	2
R77, 80	83-9520-4132-1	Resistor - Fixed, Cmp, 120 Ohm 1W 5%	2
R82, 83	83-1520-7342-1	Resistor - Fixed, Film, 82 Ohm 1/2W 2%	2
R87	83-9520-2232-1	Resistor - Fixed, Cmp 10 Ohm 1/4W 5%	1
VR1	83-1530-0389-8	Diode - Zener 10.0V 1N4708A	1
VR2	83-1530-0377-3	Diode - Zener 5.1V 1N4733A	1
VR3	83-1530-0376-5	Diode - Zener 7.5V 1N4737A	1

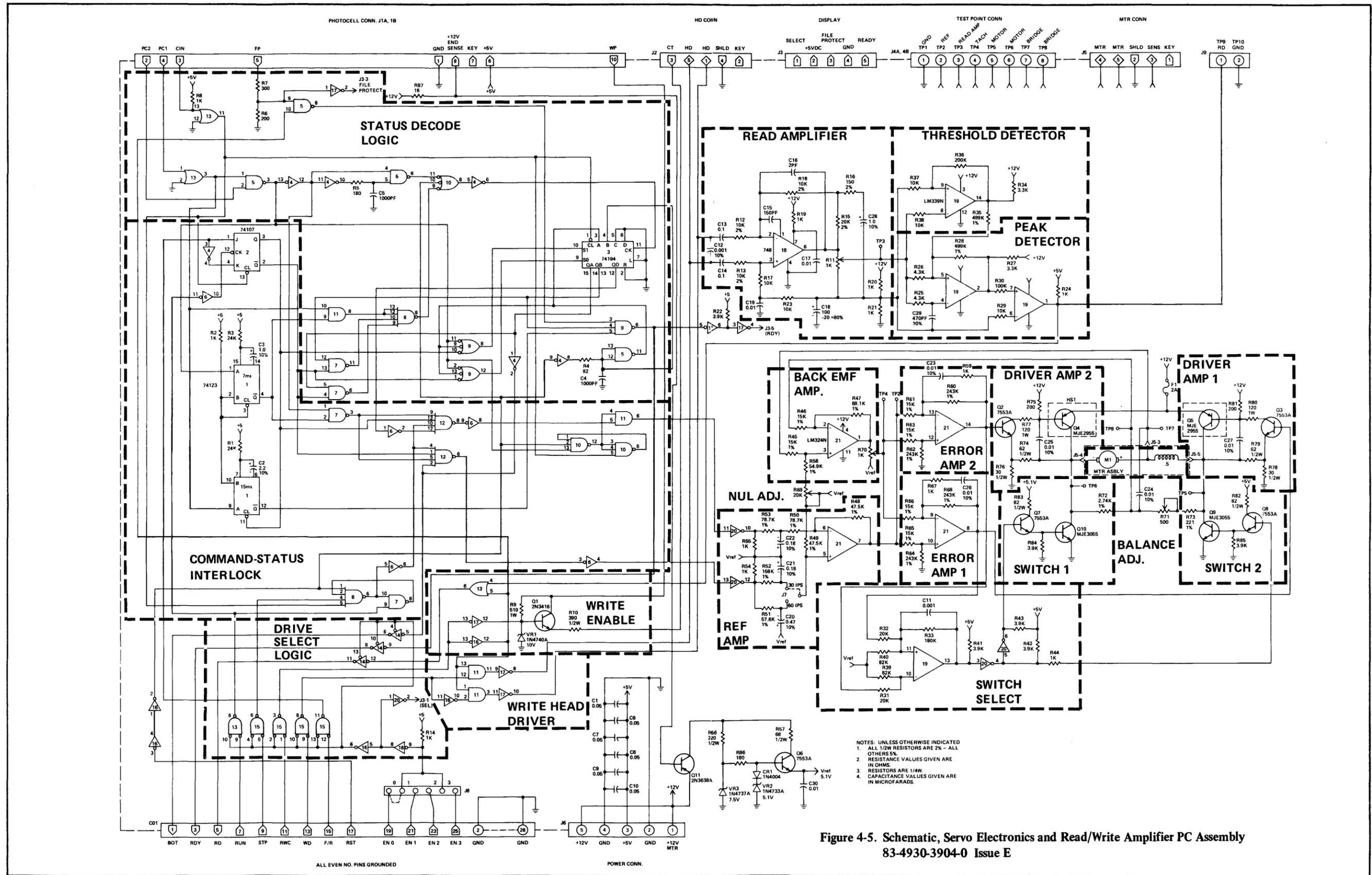


Figure 4-5. Schematic, Servo Electronics and Read/Write Amplifier PC Assembly 83-4930-3904-0 Issue E

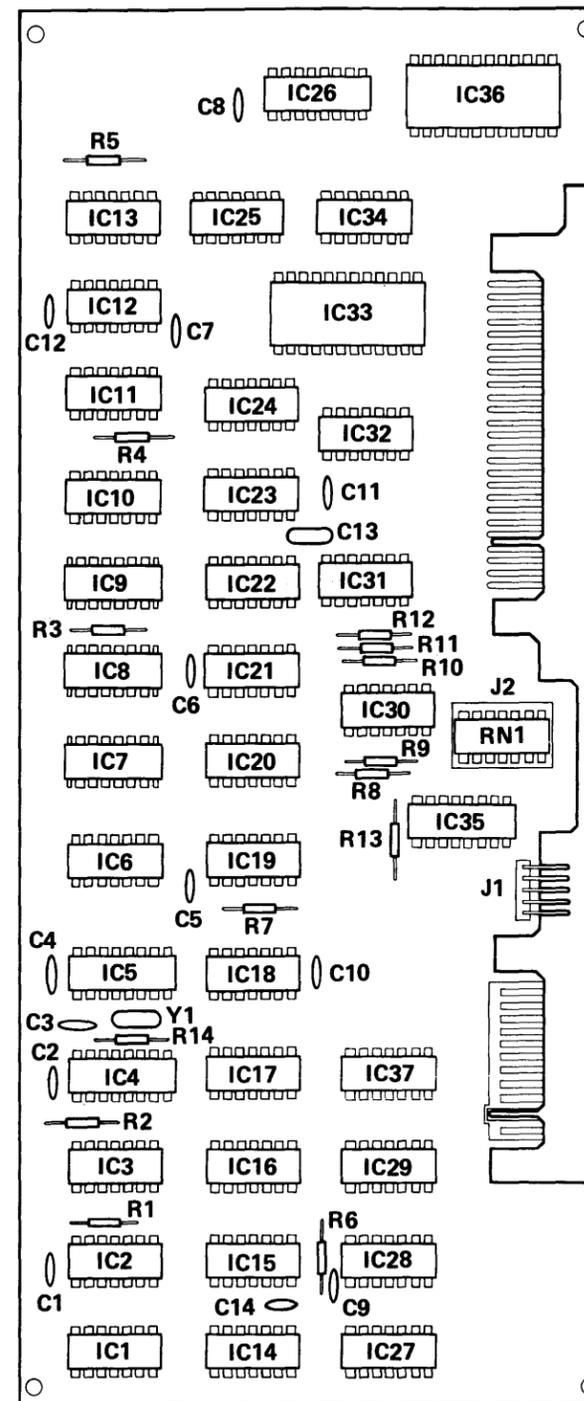
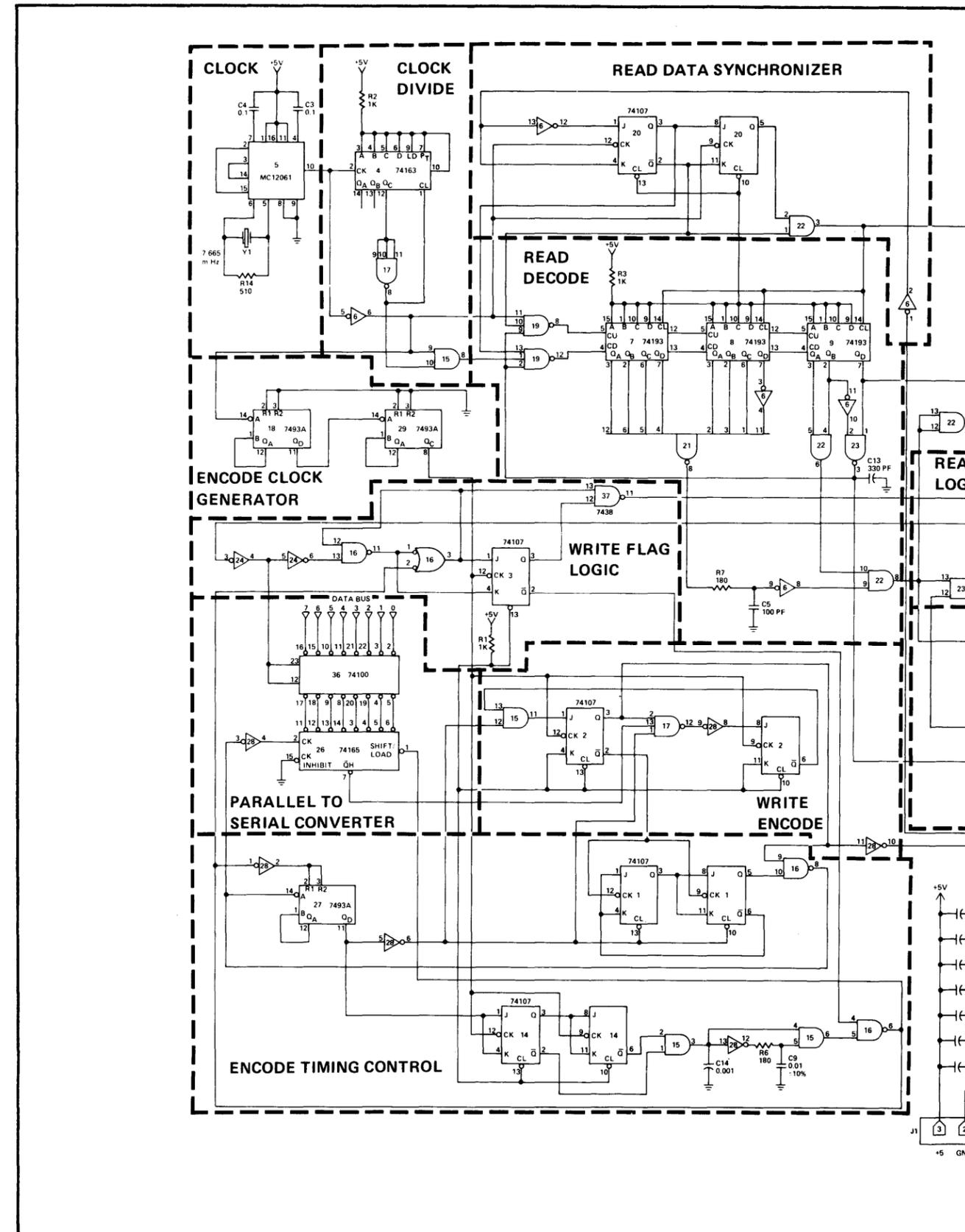


Figure 4-6. Encode/Decode Board Component Layout

Parts List, Encode/Decode PC Assembly 83-4930-3906-5, Issue C

INDEX NUMBER	PART NUMBER	DESCRIPTION	QTY.
C1, 2, 6, 8, 10-12	83-1510-2307-0	Capacitor - Fixed, Ceramic, .05 UF 10V	7
C3, 4	83-1510-1077-0	Capacitor - Fixed, Ceramic, .1 UF 10V	2
C5	83-1510-1095-2	Capacitor - Fixed, DSC, 100 PF 1000V 20%	1
C7	83-1510-1158-8	Capacitor - Fixed, Ceramic, 220 PF 1000V 10%	1
C9	83-1510-1151-3	Capacitor - Fixed, Ceramic, .01 UF 200V 10%	1
C13	83-1510-5103-0	Capacitor - Fixed, Mic, 330 PF 500V 5%	1
C14	83-1510-1024-2	Capacitor - Fixed, Ceramic, 1000 PF 1000V 10%	1
IC1-3, 14, 20	83-1530-8163-9	IC - Dual J-K SN74107N	5
IC4	78-8005-8300-3	IC - 4 Bit Synchronizer Counter SN74163N	1
IC5	83-1530-8359-3	IC - Crystal Oscillator MC12061P	1
IC6, 11, 24, 28	83-1530-8142-3	IC - Hex Inverter SN7404N	4
IC7-9	83-1530-8357-7	IC - 4 Bit Synchronizer Counter SN74193N	3
IC10, 12, 16, 23	83-1530-8060-7	IC - Quad 2 Input NAND SN7400N	4
IC13, 18, 27, 29	83-1530-8066-4	IC - 4 Bit Counter SN7493N	4
IC15, 22	83-1530-8168-8	IC - Quad 2 Input AND SN7408N	2
IC17, 19	83-1530-8143-1	IC - Tri 3 Input NAND SN7410N	2
IC21	83-1530-8061-5	IC - 8 Input NAND SN7430N	1
IC25	83-1530-8320-5	IC - Shift Register Parl Out SN74164N	1
IC26	83-1530-8172-0	IC - Shift Register Parl Load SN74165N	1
IC30	83-1530-8271-0	IC - Hex Buffer Driver SN7417N	1
IC31	83-1530-8189-4	IC - Hex Inverter Driver SN7416N	1
IC32, 34	83-1530-8356-9	IC - Quad Tri-State SN74125N	2
IC33, 36	83-1530-8355-1	IC - Latch 8 Bit BSTBL SN74100N	2
IC35	83-1530-8242-1	IC - Decoder Dual 2LN-4LN DM74155N	1
IC37	83-1530-8341-1	IC - Quad 2 Input NAND SN7438N	1
J1	83-1610-1913-4	Connector - 5 Circuit	1
J2	81-2817-4590-1	Socket - 14 Pin Dip	1
R1-3, 5, 8-13	83-9520-2088-7	Resistor - Fixed, Comp, 1K Ohm 1/4W 5%	9
R4, 6, 7	83-9520-2107-5	Resistor - Fixed, Comp, 180 Ohm 1/4W 5%	3
R14	83-9520-2139-8	Resistor - Fixed, Comp, 510 Ohm 1/4W 5%	1
RN1	83-1520-0492-1	Resistor - Fixed, Network, 330/220 Ohm	1
Y1	81-2716-6011-0	Crystal, 7.665 MHz Fund Serial Resistor	1



QTY.

7
2
1
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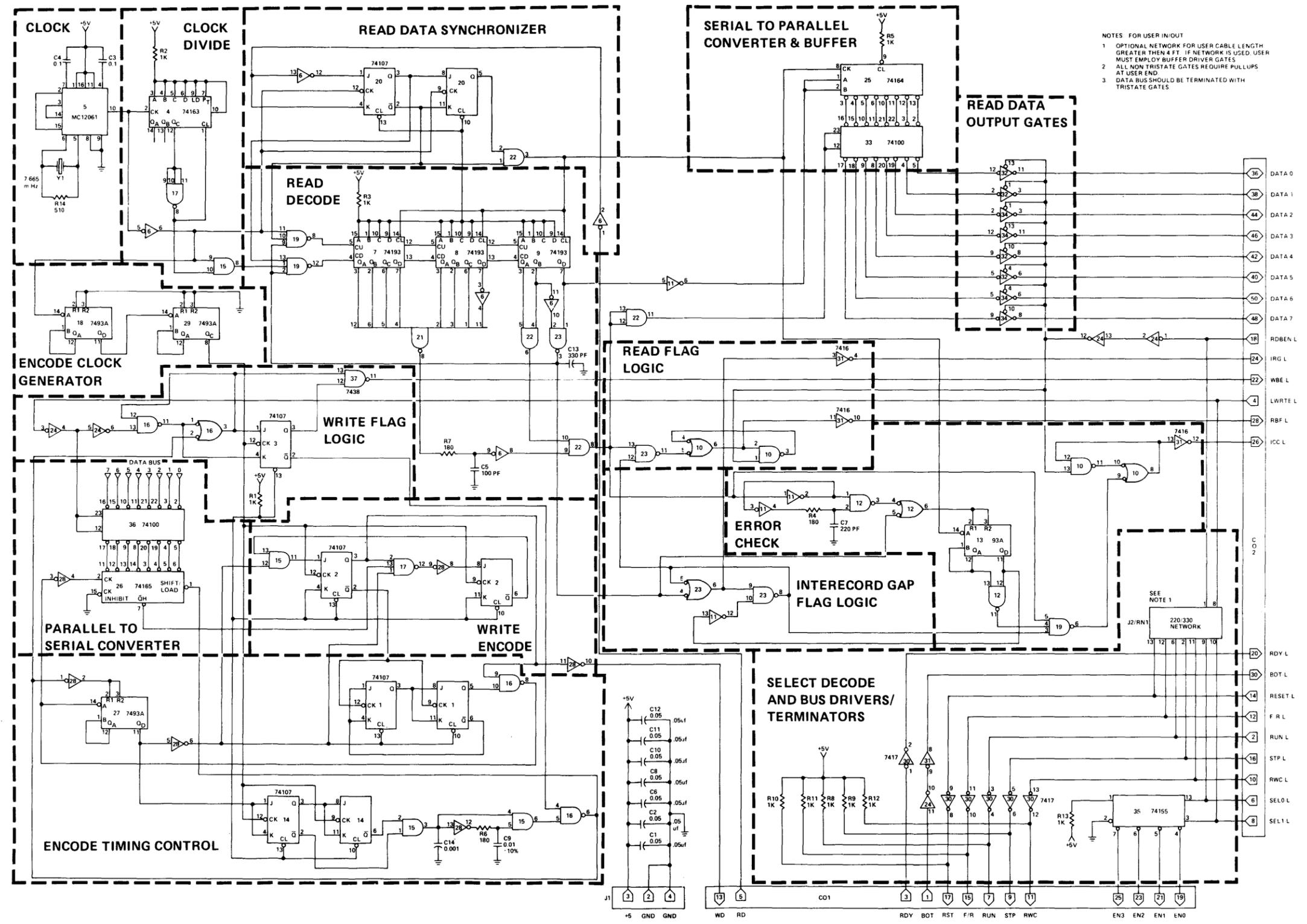


Figure 4-7. Schematic, Encode/Decode PC Assembly 83-4930-3906-5, Issue C

APPENDIX I. WARRANTY

DCD-1 DATA CARTRIDGE DRIVE WARRANTY

MINCOM DIVISION/DATA PRODUCTS, MINNESOTA MINING & MANUFACTURING CO. HEREINAFTER REFERRED TO AS 3M, WARRANTS THE EQUIPMENT COVERED HEREBY TO BE FREE FROM DEFECTS IN MATERIAL AND WORKMANSHIP FOR TWELVE (12) MONTHS FROM DATE OF ORIGINAL SHIPMENT TO PURCHASER. DURING THIS WARRANTY PERIOD 3M WILL REPAIR OR REPLACE DEFECTIVE EQUIPMENT FOB ITS PLACE OF BUSINESS WITHOUT CHARGE TO PURCHASER.

THIS WARRANTY APPLIES TO DEFECTS ARISING OUT OF NORMAL USE AND SERVICE OF THE EQUIPMENT AS SPECIFIED BY 3M. THIS WARRANTY DOES NOT COVER ABNORMAL OPERATION OF THE EQUIPMENT, ACCIDENT, ALTERATION, NEGLIGENCE, MISUSE AND REPAIRS OR SERVICING PERFORMED BY OTHER THAN 3M AUTHORIZED REPRESENTATIVES. PURCHASER SHALL UPON REQUEST BY 3M FURNISH REASONABLE EVIDENCE THAT THE DEFECT AROSE FROM CAUSES PLACING A LIABILITY ON 3M. IF THE DEFECT DID NOT ARISE FROM CAUSES PLACING A LIABILITY ON 3M, PURCHASER SHALL REIMBURSE 3M FOR EXPENSES INCURRED IN INSPECTING THE EQUIPMENT AT THE REQUEST OF PURCHASER.

THE OBLIGATION OF 3M UNDER THIS WARRANTY IS LIMITED TO REPAIR OR REPLACEMENT OF THE DEFECTIVE EQUIPMENT AND IS THE ONLY WARRANTY APPLICABLE TO THE EQUIPMENT. 3M SHALL NOT BE LIABLE FOR ANY INJURY, LOSS OR DAMAGE DIRECT OR CONSEQUENTIAL ARISING OUT OF THE USE OF OR INABILITY TO USE THE PRODUCT. NO CHANGES IN THE WARRANTY SHALL BE EFFECTIVE WITHOUT THE PRIOR APPROVAL IN WRITING OF BOTH PARTIES. THIS WARRANTY AND THE OBLIGATIONS AND LIABILITIES THEREUNDER SHALL REPLACE ALL WARRANTIES OR GUARANTEES EXPRESS OR IMPLIED ARISING BY LAW OR OTHERWISE.

MW-DCD-1

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